

22st Aerospace Testing Seminar
March 21, 2005



Thermal Testing: The Basics of Planning, Preparation, and Implementation

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Course Objectives



- **Become familiar with a systems engineering approach to thermal testing**
- **Understand the different types of thermal testing**
- **Understand the process for planning, preparing, and executing a thermal test including those involving flight hardware**
- **Understand methods of test environment simulation & temperature control**
- **Understand the role of analysis in test planning and preparation**

A Good Test is Worth 1000 Analyses



- **The operative word is “good”**
 - **A good test is one that singly focuses to meet your primary objectives & accommodates the needs of secondary objectives including functionality**
 - **Primary objectives are synthesized by asking yourself why are you conducting a test?**
 - **Generally, an empirical test is performed to improve your knowledge of some hardware of design aspect**
 - **A poorly conceived test is practically worthless**



Why Do We Perform Tests?



- To characterize parameters that are difficult to quantify analytically
- To characterize design performance/behavior

Typically, non-flight H/W

DEVELOPMENTAL TESTING

- To demonstrate in-specification hardware performance beyond allowable flight temperature range
- To uncover design or workmanship defects

Flight or QUAL H/W

ASSEMBLY PROTOFLIGHT/ QUALIFICATION

- To validate a thermal design
- To demonstrate functionality at expected temperature

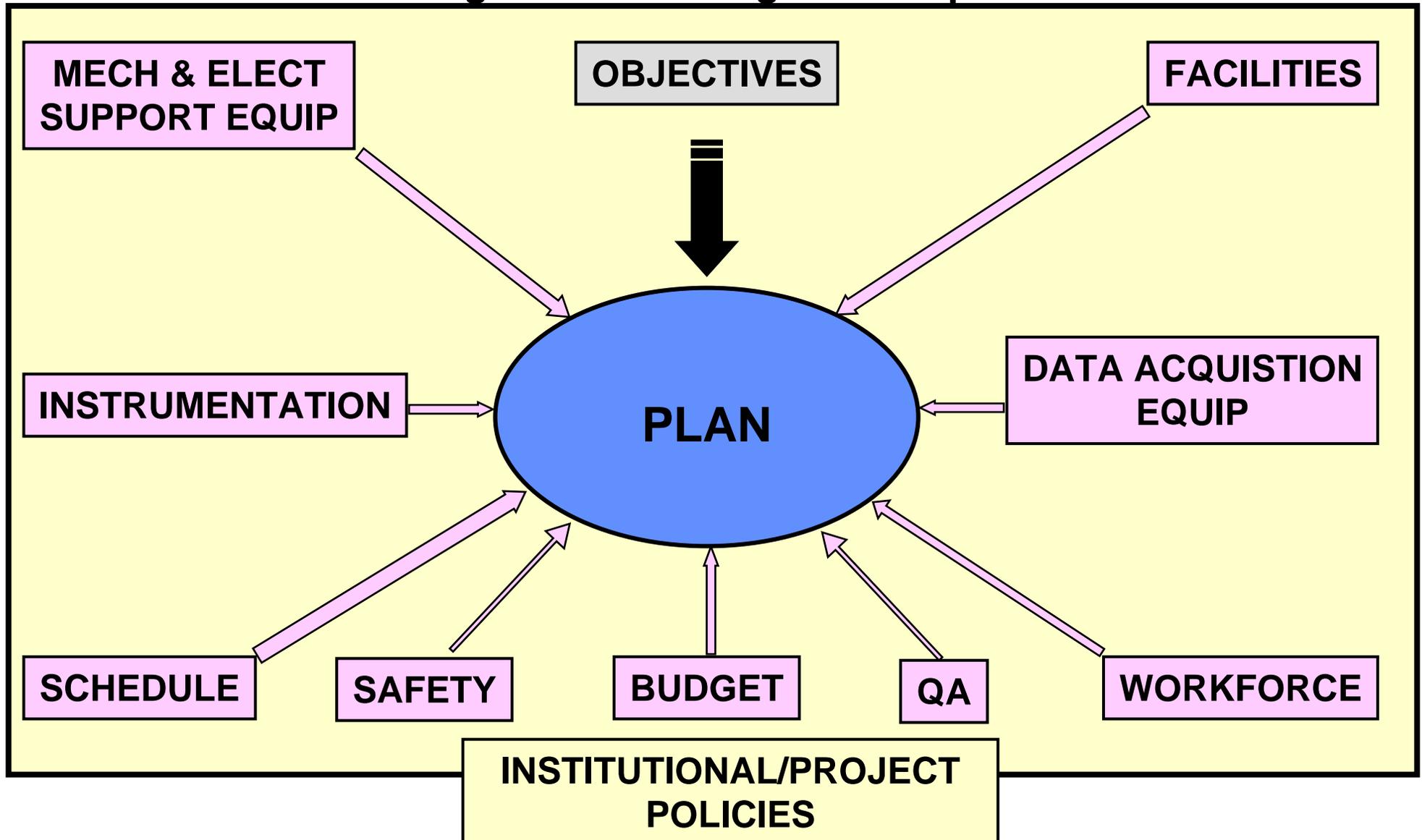
Flight or QUAL H/W

SYSTEM- OR ASSEMBLY-LEVEL THERMAL BALANCE

We Don't Plan to Fail, We Fail to Plan



- At the heart of a “good” test is a good test plan



What Makes a “Good” Test



- **Well defined objectives (primary & secondary)**
- **A test case matrix that directly maps into the objectives**
- **Understanding your role & duties in planning, preparing, executing, and documenting the test**
- **Understanding your resource constraints**
 - **Financial budget**
 - **Schedule**
 - **Facilities including instrumentation & data acquisition**
 - **Mechanical & electrical ground support equipment**
 - **Workforce**
- **Tapping into the test experiences of others**
 - **Conduct peer reviews of your plan & approach**

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Types of Thermal Testing



There Are Three General Categories



DEVELOPMENTAL TESTING

- To characterize parameters that are difficult to quantify analytically
- To characterize design performance/behavior

- Thermal environment is known
- Temperature is a dependent parameter

ASSEMBLY PROTOFLIGHT/ QUALIFICATION OR FLIGHT ACCEPTANCE

- To demonstrate in-specification hardware performance beyond allowable flight temperature range
- To uncover design or workmanship defects

- Temperature is an independent parameter; specified *a priori* along with dwell times, ramp rate, & number of cycles

SYSTEM- OR ASSEMBLY-LEVEL THERMAL BALANCE

- To validate a thermal design
- Empirical validation is the goal
- To demonstrate functionality at expected temperatures

- Thermal environment is known
- Temperature is a dependent parameter

Thermal Development Testing

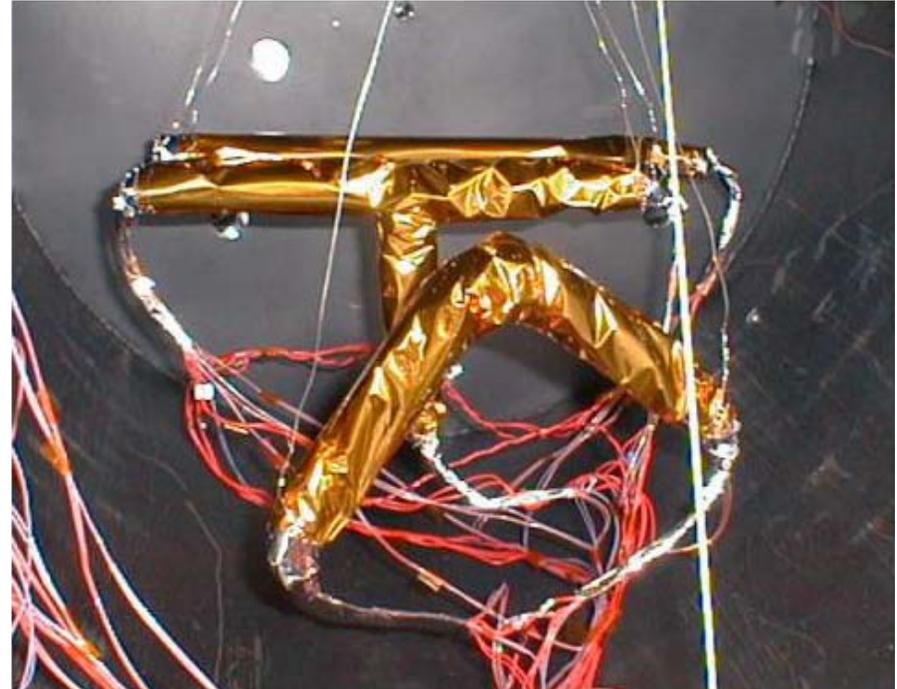


- **Used to assist design development, especially for situations that are difficult to characterize analytically & are key thermal design drivers**
 - Insulation performance, especially MLI blankets
 - Interface contact conductance
 - Bearing conductance
- **Used to expand thermal design space beyond a “single point”**
 - Investigate if a design approach is feasible (“proof-of-concept”)
 - Determine design sensitivity to key thermal parameters
- **This type of testing aims to reduce design deficiency risk**
- **Typically, non-flight hardware used for test article**
 - You must understand your needs for the fidelity of the test article (thermal control model or thermal mock-up)

MER Propellant Line Thermal Blanket Development Test



- **Objective**
 - To characterize effective emittance for a series of blanket geometries
 - Straight
 - Tee
 - Elbow
- **Results were imported into analytical model for heater sizing**
 - Thermal balance for a propellant line zone is on the order of a few tenths of Watts

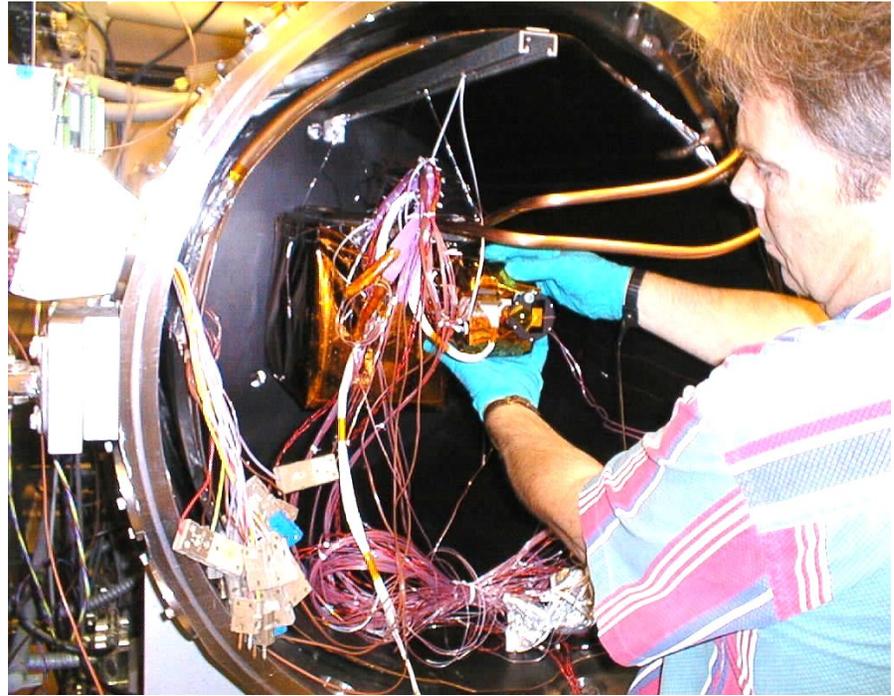


APEX Camera & Electronics Thermal Development Test



- **Objectives**

- To determine amount of Mars nighttime survival heater power for the camera
- To determine amount of camera warm-up heater power
- To determine camera thermal response to transient changes in atmospheric & effective sky temperatures
- To determine effectiveness of electronics thermal insulation
 - Novel approach that uses stagnant in-situ Mars atmosphere
- To characterize electronics heat losses through insulation, mounting, and cabling



- **Results**

- Adopted novel insulation approach as baseline
- Verified survival & warm-up heater camera power
- Correlated analytical model to transient test data

Assembly Protoflight/Qualification OR Flight Acceptance Testing

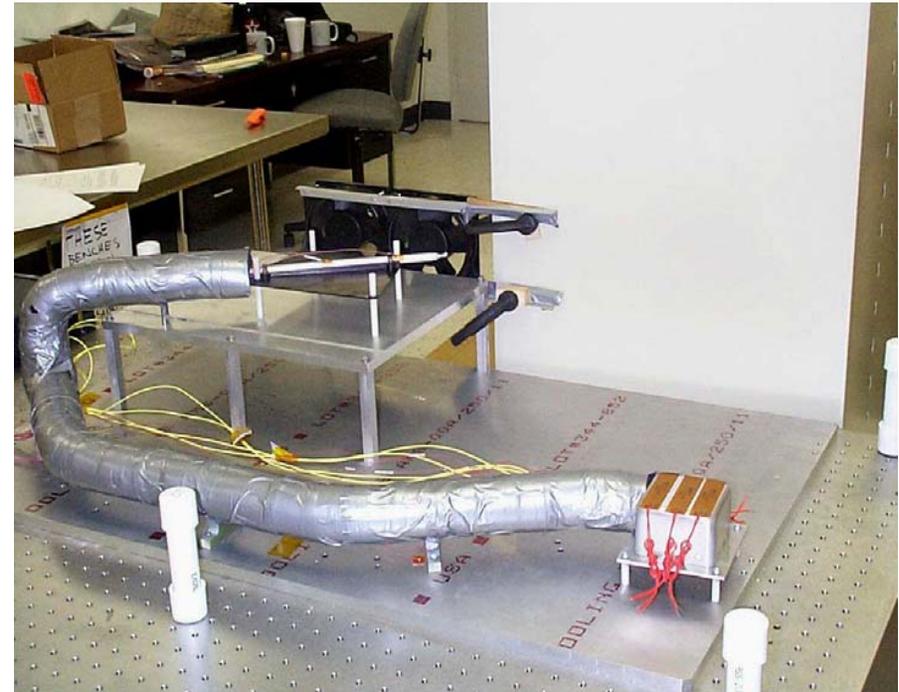


- **Used to demonstrate assembly workmanship and design reliability**
 - Sometimes referred as “margin testing”
- **Test temperature levels, dwell times, temperature ramp rates, and number of thermal cycles are dictated by institutional or project policies**
- **Traditional test program is QUAL/FA or PF**
 - EM hardware subjected to QUAL testing
 - FLT hardware subjected to FA testing
 - OR FLT hardware subjected to PF testing

Mars'01 Lander Heat Pipe Flight Acceptance Test



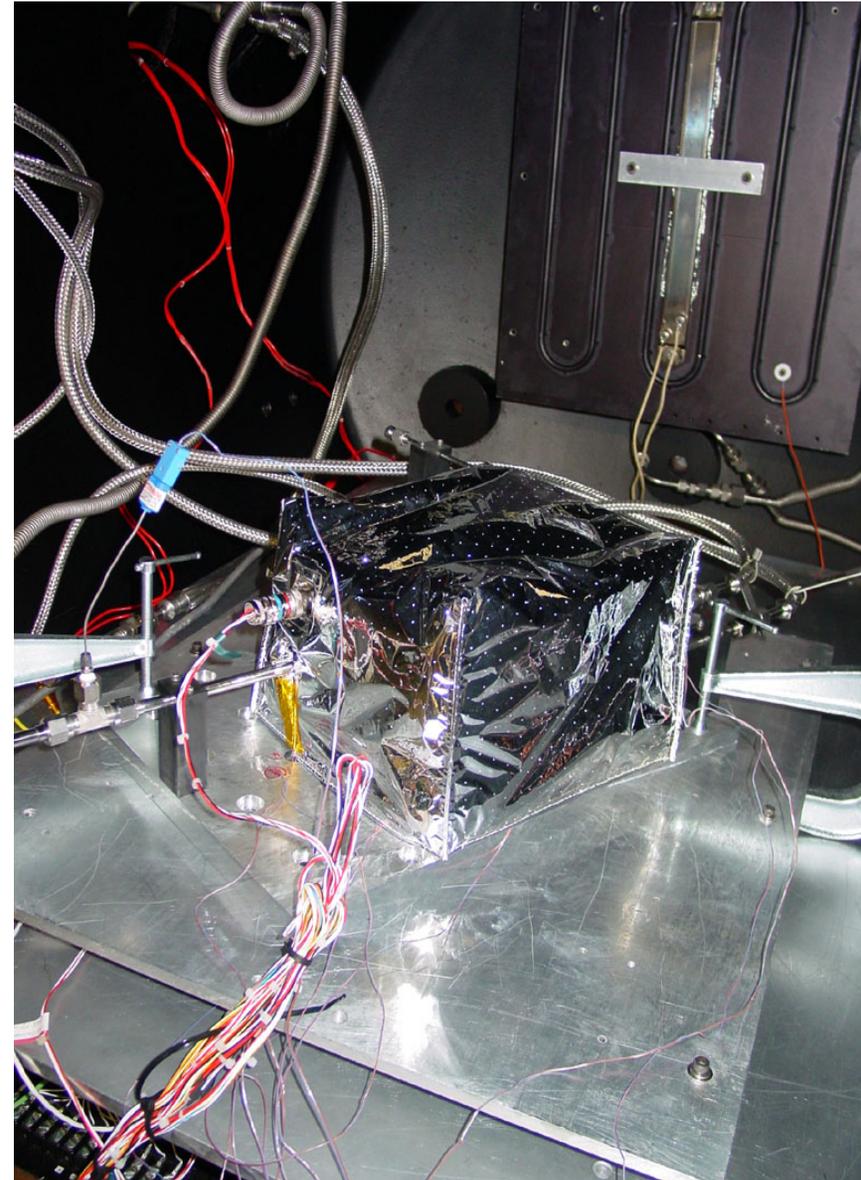
- **Objectives**
 - Validate flight units function in reflux mode in-air
 - Validate capability to transfer 1 watt under various tilt angles
 -
 - Quantify thermal gradients along heat pipe
 - Compare pre-start-up thermal gradients to analytical predictions
- **Results demonstrated that flight units would transfer sufficient heat during cruise to Mars**
 - Hardware accepted for flight



MER Integrated Pump Assembly Thermal Protoflight Testing



- **Objective**
 - Demonstrate in-specification performance (pump ΔP & flow rate) over temperature ranges greater than allowable flight temperature (AFT) limits
 - Operating AFT limits
 - -20°C to +30°C
 - Operating Protoflight (PF) limits
 - -35°C to +50°C
 - Dwell durations
 - Cumulative 24 hours cold
 - Cumulative 50 hours hot
 - Number of thermal cycles
 - 3 times lifetime requirement
 - 3 test cycles
- **Test results met objectives**
 - Hardware accepted for flight



System- OR Assembly-Level Thermal Balance Testing



- **Used for thermal design validation and hardware functionality in expected thermal environment**
 - “Validation” versus “Verification”
 - First discovery of a design deficiency is very costly (budget & schedule) to rectify at this point
 - Hardware functionality includes thermal items such as heaters, thermostats, temperature sensors, heat pipes/CPLs, & pumps
- **Two basic approaches**
 - **Empirical**
 - Bounding worst-case thermal environments
 - **Combination of test & analysis**
 - Specified hot & cold thermal environment to obtain data for analytical model correlation
 - Analytical model utilized to demonstrate design requirement compliance

GALEX Instrument Thermal Balance Testing



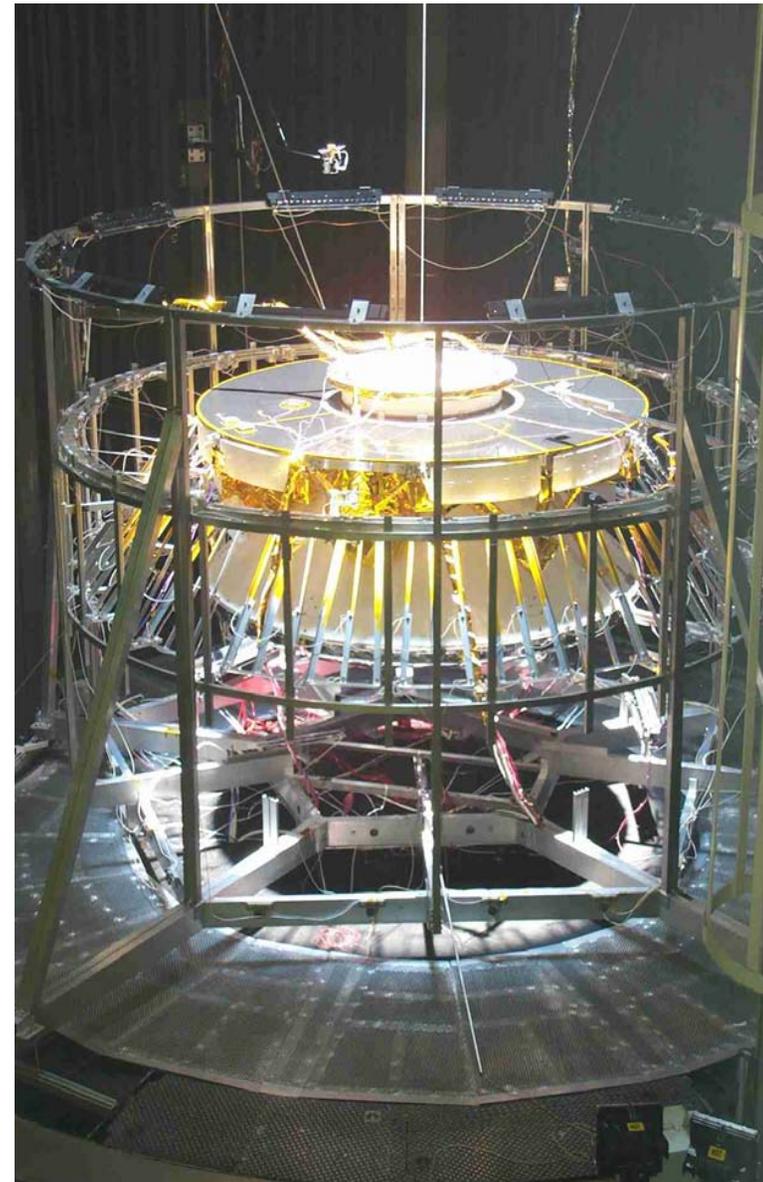
- **Objectives**
 - Validate instrument thermal design for worst-hot & -cold Earth orbit conditions
 - Validate survival (primary & secondary) heater string operation
 - Validate optical performance
- **Design validation was empirical**
 - Test results met objectives
 - Design maintained allowable flight temperatures for extreme environmental cases
 - Primary & secondary survival heater strings validated



MER Cruise Thermal Balance Testing



- **Objectives**
 - **Validate thermal design for mission worst-hot & -cold conditions**
 - Solar simulation used
 - IR lamps used for off-sunpoint simulation
 - **Validate mechanical pump fluid loop operation**
 - **Validate primary & secondary thermostatic heater strings**
- **Design validation was empirical**
 - **Test objectives met**
 - **Uncovered swapped primary & backup thermostats on four assemblies**
 - **Determined –Z sun sensor did not require silverized Teflon tape**



MER Mars Surface Thermal Balance Testing



- **Objectives**

- To perform representative steady-state & transient cases to gather empirical data for analytical model correlation
 - Simulation of Mars surface environment extremely challenging (e.g., diurnal solar heating, wind simulation, 3/8 gravity field, CO₂ atmosphere)
- To validate critical deployments & releases at cold temperature
- To perform science instrument calibration at various temperatures

- **Design validation used a combination of test & analyses**



- **Results**

- Test data confirmed development test results that WEB thermal design is robust
- Provided empirical data for actuator heater warm-up validation
- Demonstrated critical deployments & science calibrations

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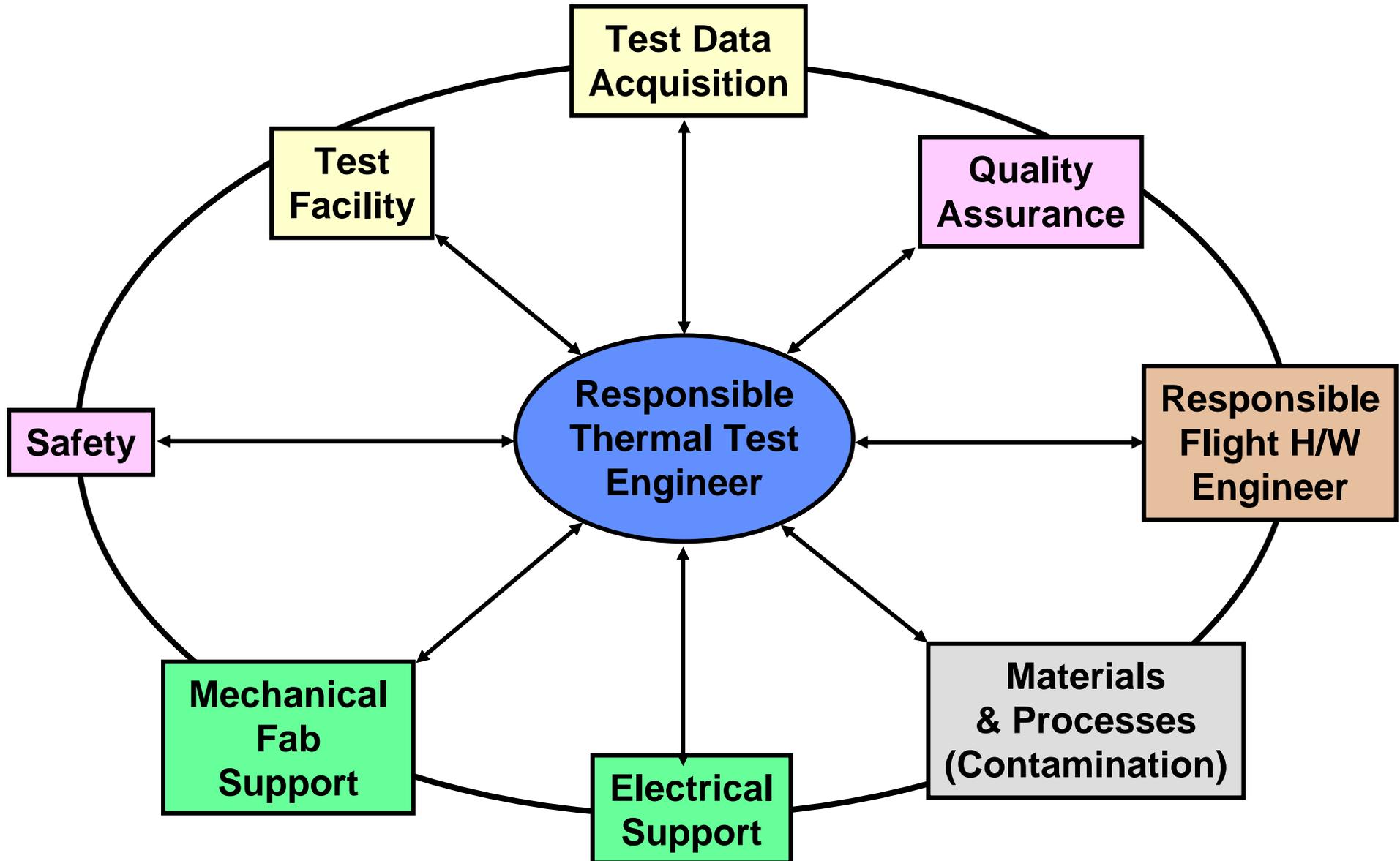
General Planning Issues



 THE AEROSPACE CORPORATION



The World According to the Thermal Test Engineer

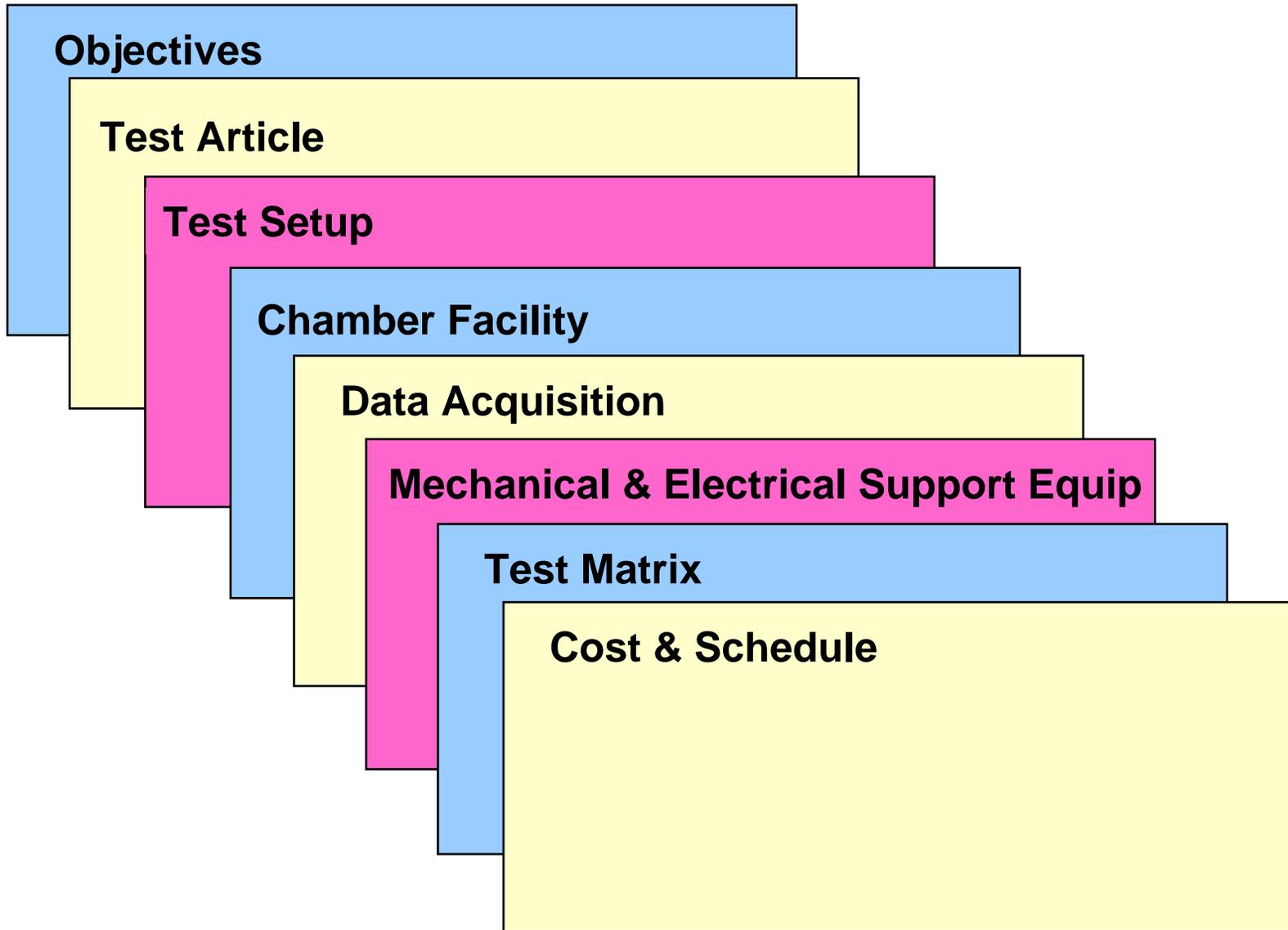


Your Role as Thermal Test Engineer



- **Understanding your role as responsible thermal test engineer**
 - **Clear and decisive communication with your interfaces is critical**
 - Be proactive; attend to issues quickly & prevent new ones from arising
 - **Develop well-defined and verifiable test objectives**
 - This will define how the test will be simulated and instrumented
 - Identify special tests
 - **Know your responsibilities for ensuring hardware & personnel safety**
 - **Planning becomes more intertwined with other parties as you move from a thermal development test to an assembly-level qualification/acceptance test to a system-level thermal test**
- **Test planning involves a significant amount of your time & effort so allocate ample time in your schedule**

Elements of the Test Plan



Planning: “Rome Wasn’t Built in a Day” (1/3)



- **Why is a plan needed?**

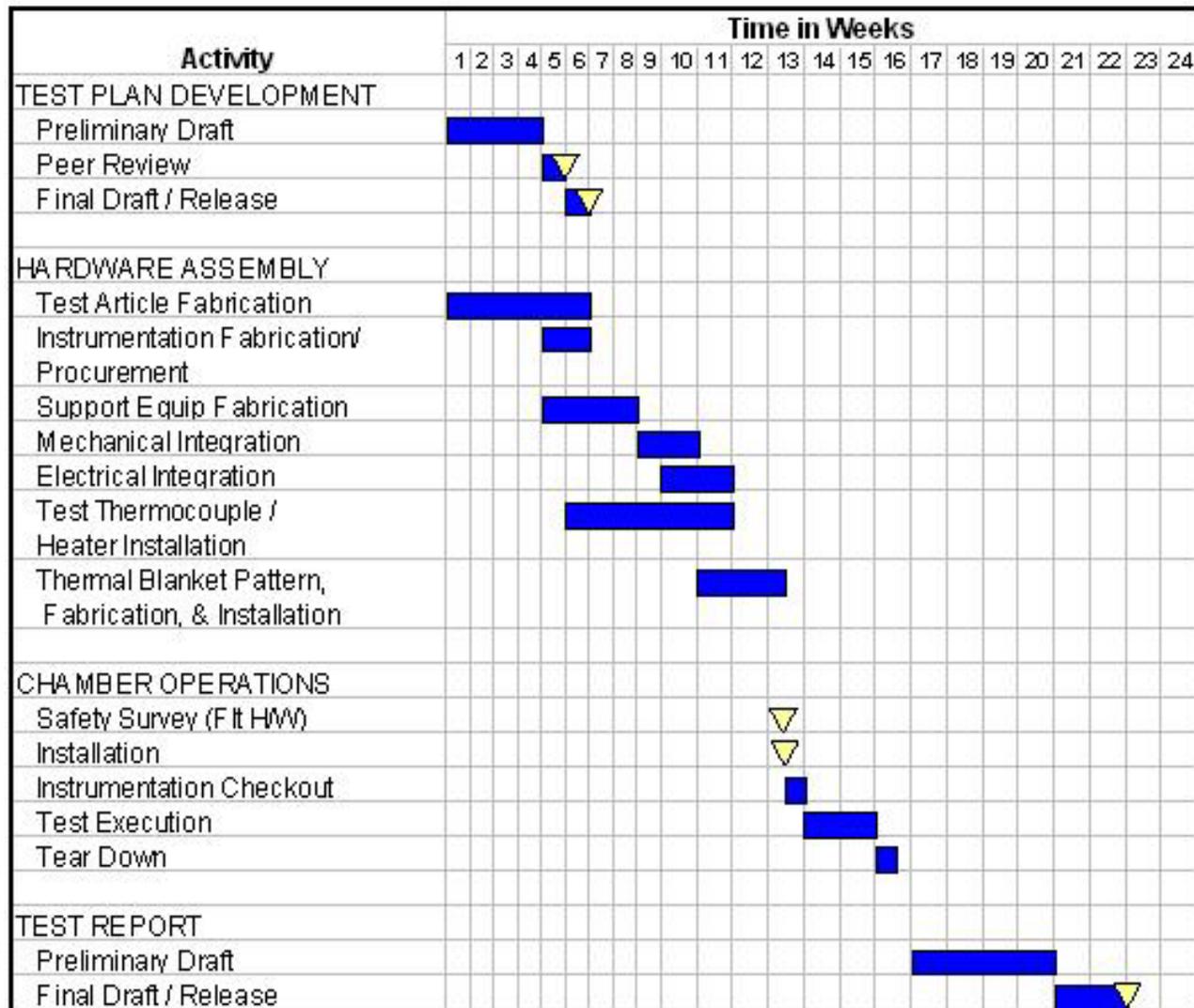
- **Tool that initiates & guides the test planning & preparation process**

- **Acts as the driver to totally engage the responsible thermal test engineer**
 - **Allows you to stay on top of all test aspects, even as the test evolves**
 - **Stimulates feedback from the key interfaces**
 - **Leads to a more efficient use of resources**

Planning: “Rome Wasn’t Built in a Day” (2/3)



- How long does the planning & preparation process take?
 - Schedule shown is typical of development testing



Planning: “Rome Wasn’t Built in a Day” (3/3)



- **High-level schedule for system thermal testing (STT)**

Event	Timing
Preliminary STT Concept	Thermal PDR
STT Preliminary Plan Peer Review	4 Weeks Prior to Thermal CDR
Preliminary STT Plans	Thermal CDR
Preliminary STT Plan Release	2 Weeks Prior to ETRR
Preliminary STT Plan Summary	ETRR
STT Final Plan Peer Review	6 Weeks Prior to STT Start
STT Final Plan Project Review	4 Weeks Prior to STT Start
STT Final Plan Sign-off	2 Weeks Prior to STT Start
STT Preliminary Results Presentation	1 Week After STT End
STT Final Test Report Peer Review	10 Weeks after STT End
STT Final Test Report Release	3 Months After STT End

Objectives: “The Chicken is Involved for Eggs; The Pig is Committed for Bacon”



- **Test objectives are the very core of the test**
 - Specific
 - Verifiable from the test results
- **Objectives fall into two categories**
 - Primary
 - Secondary or Special
- **Primary objectives**
 - Very often, linked to Project Level 3 & 4 requirements
 - “To determine the survival heater power for the worst-case cold Martian surface thermal environment”
 - “To demonstrate in-specification telescope optical performance at the hot and cold flight acceptance temperature levels”
 - “To verify that the temperature control design will maintain the spacecraft and all its elements within allowable flight temperature ranges while operating over the environmental extremes expected for the mission”

Objectives: “The Chicken is Involved for Eggs; The Pig is Committed for Bacon”



- **Secondary or special objectives**

- Tests present unique opportunities to obtain additional empirical information to more fully understand the thermal design
- If properly planned, the gathering of this information will be of minimal impact to the primary test flow

- **Examples**

- **Sensitivity of temperature to power**
 - › Optimize size of flight heaters
 - › Assess effect of poorly-known or degraded thermal properties
 - › Assess heater element failure
- **Sensitivity of temperature to boundary conditions**
- **Determine temperature changes after switching from primary to redundant equipment**
- **Obtain information for mission operations**
 - › How long can heaters (or equipment) be turned off?
 - › How long does it take a heater to do its warm-up job?

Objectives: “The Chicken is Involved for Eggs: The Pig is Committed for Bacon”



- **“Permissible” temperature limits when using flight hardware**
 - **Although there are established Level 3 allowable flight temperature limits, there is no universally accepted interpretation of permissible limits during test**

 - **Permissible test limits are the criteria for the generation of problem reporting documentation**
 - **A balance between hardware safety & test flexibility must be struck**
 - **Flight hardware should be only exposed to temperature levels within previous environmental test experience**
 - **At JPL, flight acceptable (FA) test limits have constituted permissible test limits**
 - › Enabled testing to continue when marginal allowable flight temperature violations occurred
- **You must unambiguously define these limits & reach agreement with the appropriate parties before the test begins**

Test Article: What Is It That We're Testing?

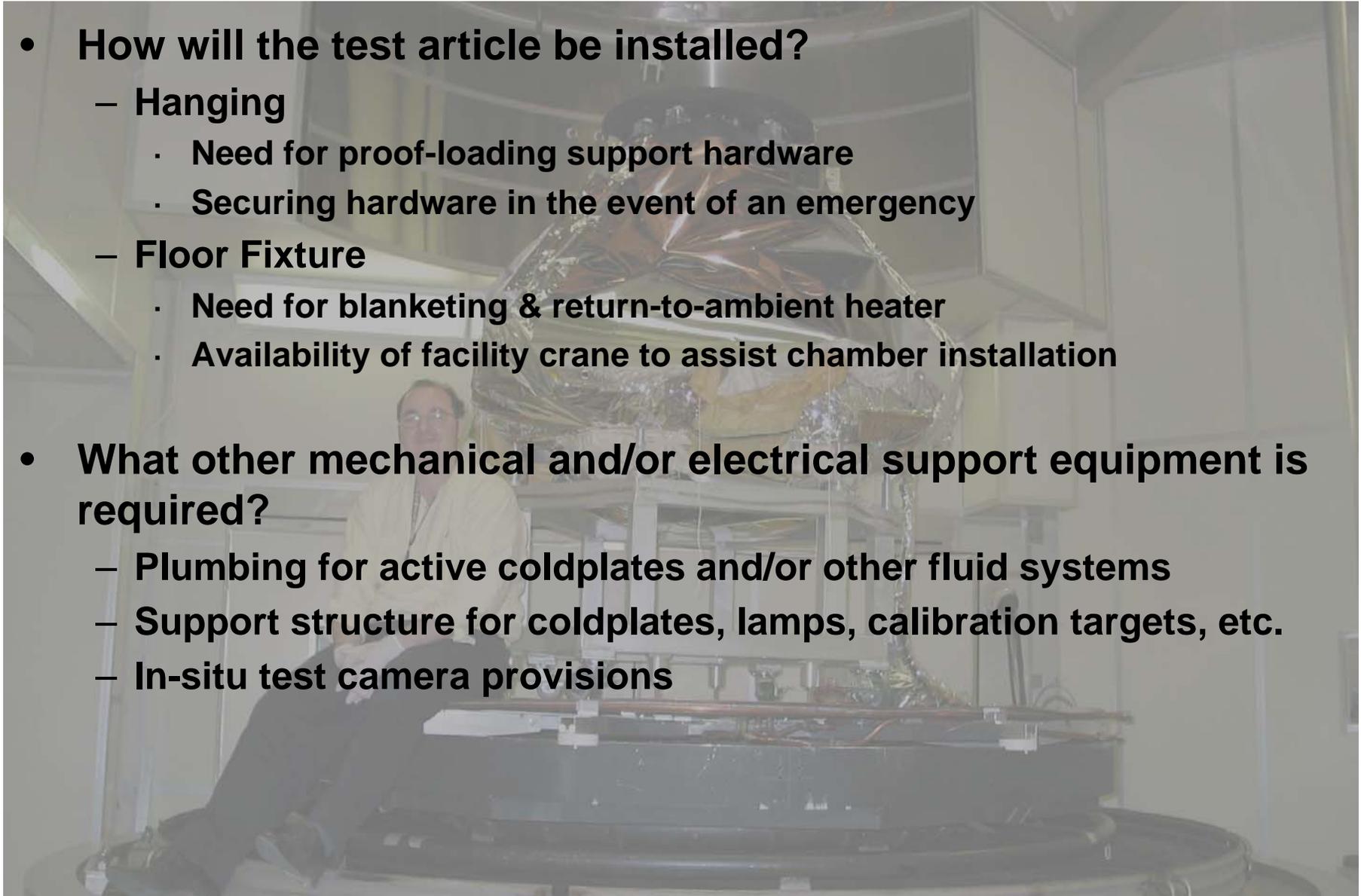


- **Developmental testing usually uses non-flight hardware**
 - You must define the key thermal requirements for the fabrication of the test article
 - How important is fit & form?
 - How important is the article mass?
 - How will internal power be simulated?
 - Replication of heat transfer paths including radiation (i.e., surface finish)
 - Egress of test heater & temperature sensor cabling
 - Avoid cadmium-plated fasteners (not vacuum qualified)
 - Use of flight hardware will complicate the test planning
- **Protoflight/Qualification & Flight Acceptance testing involves flight hardware**
- **System-level testing involves primarily flight hardware**
 - However, EM or QUAL units may be used as substitutes when flight hardware is late
 - You will need to assess the impact to your objectives if such substitutions occur

Test Set-up Considerations



- **How will the test article be installed?**
 - **Hanging**
 - Need for proof-loading support hardware
 - Securing hardware in the event of an emergency
 - **Floor Fixture**
 - Need for blanketing & return-to-ambient heater
 - Availability of facility crane to assist chamber installation
- **What other mechanical and/or electrical support equipment is required?**
 - **Plumbing for active coldplates and/or other fluid systems**
 - **Support structure for coldplates, lamps, calibration targets, etc.**
 - **In-situ test camera provisions**



Test Facilities Considerations



- **Ensure that the facility has been certified for the environmental testing that you will conduct**
 - Facility safety survey
 - Cleanliness
- **Select minimally-sized chamber subject to:**
 - Test objectives
 - Critical mechanical clearances to chamber wall
 - Accommodation of other support hardware
- **Most thermal tests require a cold shroud**
 - Understand temperature ranges & stability
 - Understand impact of close proximity of the test article to shroud
 - Do you also require a door shroud?
- **Optical test articles may require a chamber window**
 - Special thermal considerations to reduce impact of window
 - Reduce aperture area with thermal blanketing or highly reflective shield
 - Use a long-length chamber & place test article as far from the window as possible
- **Ensure that the surrounding external chamber area is sufficient for staging and accommodation any GSE**

Test Data Acquisition Planning (1/2)

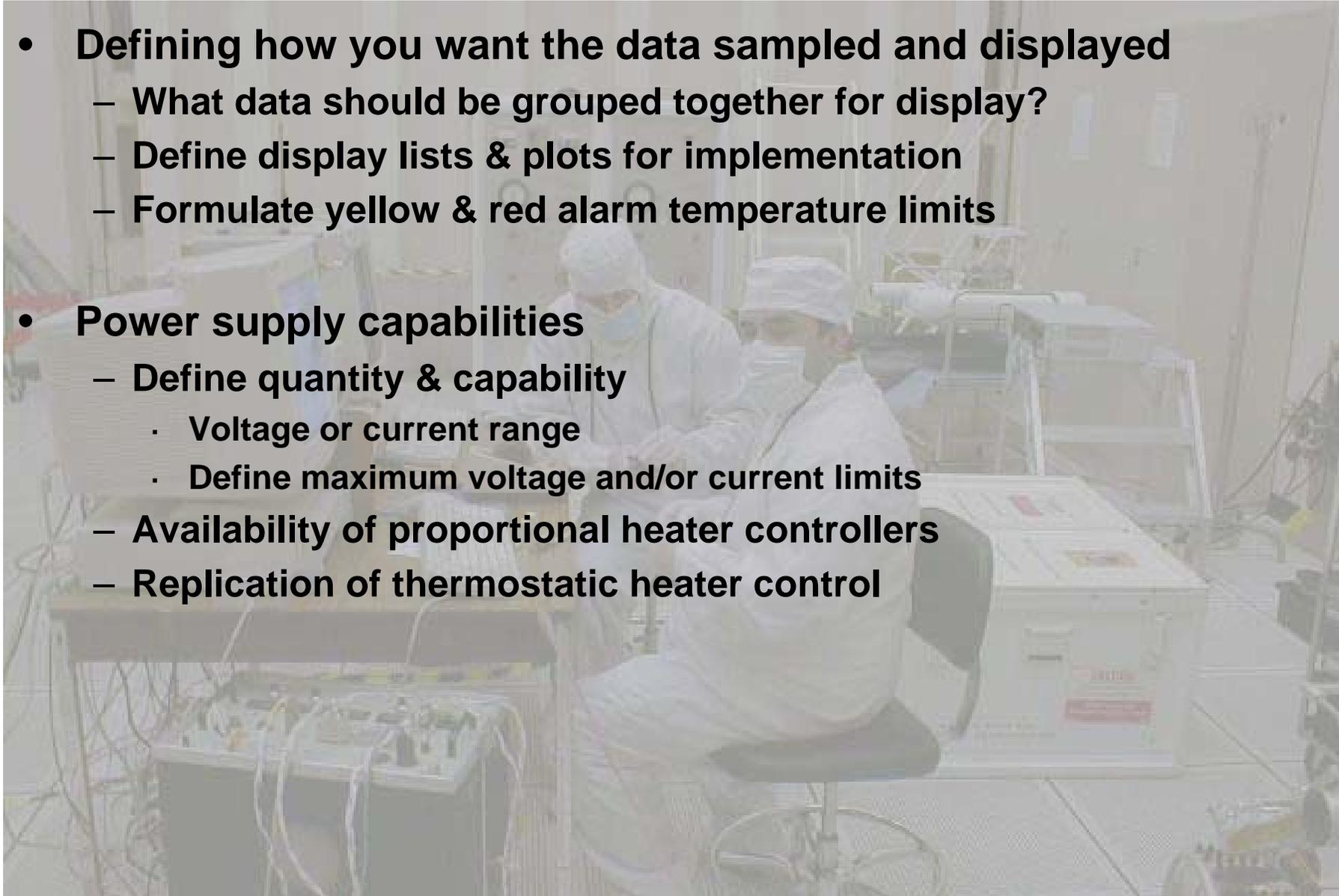


- **How do you determine where the thermocouples & test heaters are located?**
 - Temperature data that will directly lead to verifying your objectives
 - Temperature data that will provide a better understanding of your design
 - Temperature data that will not be measured in-flight
 - What hardware requires safeguarding in event of a facility failure or test problem?
 - Consider supplementing flight heaters where practical
 - Accelerate achievement of steady-state
 - Accelerate transition to return-to-ambient
 - Consider *in-situ* massive support equipment which need warm-up acceleration upon return-to-ambient
- **Defining computed data from raw test data**
 - Maximum, minimum, & average temperatures
 - Spatial temperature difference
 - Temperature rate of change
 - Internal power dissipation

Test Data Acquisition Planning (2/2)



- **Defining how you want the data sampled and displayed**
 - What data should be grouped together for display?
 - Define display lists & plots for implementation
 - Formulate yellow & red alarm temperature limits
- **Power supply capabilities**
 - Define quantity & capability
 - Voltage or current range
 - Define maximum voltage and/or current limits
 - Availability of proportional heater controllers
 - Replication of thermostatic heater control



Mechanical & Electrical Support Equipment



- **Development testing will require a significant amount of mechanical fabrication support**
 - **Get them involved with the planning process as early as possible**
 - **Seek feedback about feasibility of thermal mock-up design & fabrication**
 - › Includes support hardware & thermal blanketing
- **PF/QUAL/FA & system-level testing will require flight technicians to assemble and integrate flight hardware for the test**
 - **Get involved to understand the mechanical & electrical integration flow**
 - **Identify the need for the fabrication of support hardware**
 - **Develop a mutually acceptable schedule**
 - **Identify key times where test instrumentation & blanketing can be installed**

Test Matrix Development Process (1/2)



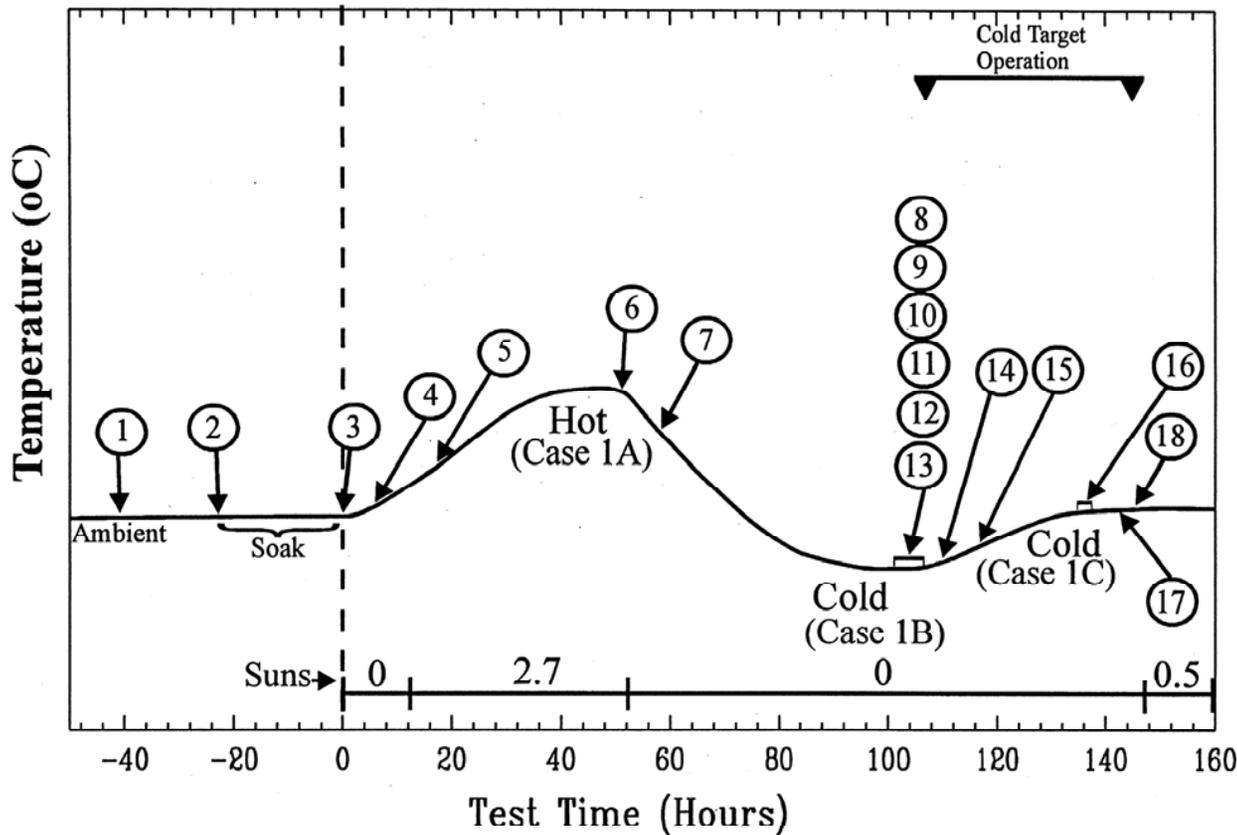
1	Pumpdown and Accurate Thermal Balance	Thermal Design verification at nominal SS PA conditions	1:52	0	<10 ⁻⁵ tor	LN ₂	390	No	late cruise	Ne	Cruise 5	Pump A	GSE	Temp to Ambient - Hot	8
Cold Cases															
2	Backup Thermal Balance	Thermal Design verification at nominal SS PA conditions	1:52	0	<10 ⁻⁵ tor	LN ₂	390	No	as needed	Ne	Cruise 5	Pump A	GSE	Temp to Ambient - Hot	40
3A	Flight Software Setpoint Test	Thermal Design verification at nominal SS PA conditions	1:52	0	<10 ⁻⁵ tor	LN ₂	390	No	late cruise	Ne	Cruise 5	Pump E	GSE	T-Zero	12
3B	SSPA Swallow	Thermal Design verification at nominal SS PA conditions	1:52	0	<10 ⁻⁵ tor	LN ₂	390	No	late cruise	Ne	Cruise 5	Pump E	GSE	T-Zero	12
3C	Backup Heater Functional Test	Thermal Design verification at nominal SS PA conditions	1:52	0	<10 ⁻⁵ tor	LN ₂	390	No	as needed	Ne	Cruise 5	Pump E	GSE	T-Zero	10
4	S/C Functional Cold Environment	Thermal Design verification at nominal SS PA conditions	1:52	0	<10 ⁻⁵ tor	LN ₂	390	No	as needed	Ne	Cruise 5	Pump E	GSE	T-Zero	10
5	Prop System Cold Environment	Thermal Design verification at nominal SS PA conditions	1:52	46	<10 ⁻⁵ tor	LN ₂	412	Yes	late cruise	Ne	Cruise 5	Pump A	GSE	Temp to Ambient - Hot	36
EDL Cases															
6	TCM-6	Thermal Design verification at nominal SS PA conditions	1:52	46	<10 ⁻⁵ tor	LN ₂	412	Yes	Pre-EDL	Yes (max)	Cruise 5	Pump A	GSE	x-Cont	24
7	EDL Functional Test	Thermal Design verification at nominal SS PA conditions	1:52	46	<10 ⁻⁵ tor	LN ₂	412	Yes	EDL	Yes (max)	OFF	Tr/Eat	LEat	x-Cont	4
8	HRS Verification Simulation & Non-Op Test	Thermal Design verification at nominal SS PA conditions	1:52	46	<10 ⁻⁵ tor	LN ₂	412	Yes	EDL	Yes (max)	OFF	Data?	T-Zero	10	
Hot Cases															
9	Prop System Thermal Balance	Thermal Design verification at nominal SS PA conditions	1:52	0	<10 ⁻⁵ tor	LN ₂	1272	No	Early Cruise	Yes (nom)	Cruise 1	Pump A	GSE	Temp to Ambient - Hot	36
10	Backup Thermal Balance	Thermal Design verification at nominal SS PA conditions	1:52	0	<10 ⁻⁵ tor	LN ₂	1272	No	as needed	Yes	Cruise 1	Pump A	GSE	Temp to Ambient - Hot	36
11	WEB Temp Fault Protection Test	Thermal Design verification at nominal SS PA conditions	1:52	0	<10 ⁻⁵ tor	LN ₂	1272	No	as needed	Yes	Cruise 1	Pump A	GSE	Temp to Ambient - Hot	4
12	S/C Functional Hot Environment	Thermal Design verification at nominal SS PA conditions	1:52	0	<10 ⁻⁵ tor	LN ₂	396	Yes	as needed	Yes	Cruise 1	Pump E	GSE	T-Zero	10
13	Backup Chamber	Thermal Design verification at nominal SS PA conditions	1:52	0	<10 ⁻⁵ tor	LN ₂	396	Yes	as needed	Yes	Cruise 1	Pump E	GSE	T-Zero	10
<input type="checkbox"/> cases repeated for CSAS configuration (5 cases)			Functional Test Time (hrs): 20 (days) 0.8										Total Test Time (hrs): 243 (days) 10.1		

- **The challenge: Determine how best to incorporate all of the test objectives within an allocated test time period**
- **The resolution process involves the stakeholders of each test objective**
- **This process becomes more complex when a system-level thermal test is involved**
- **The process**
 - Identify major test divisions on a timeline
 - Identify when specific events occur
- **Focus on first accommodating primary objectives & then finding non-intrusive time periods (from a thermal perspective) for special tests & objectives**
- **Ideally, use analysis to assist test case & transition durations**
- **The “design” analytical model must be transformed into a “test” analytical model**
- **This is a significant effort that you must include in your planning**

Test Matrix Development Process (2/2)

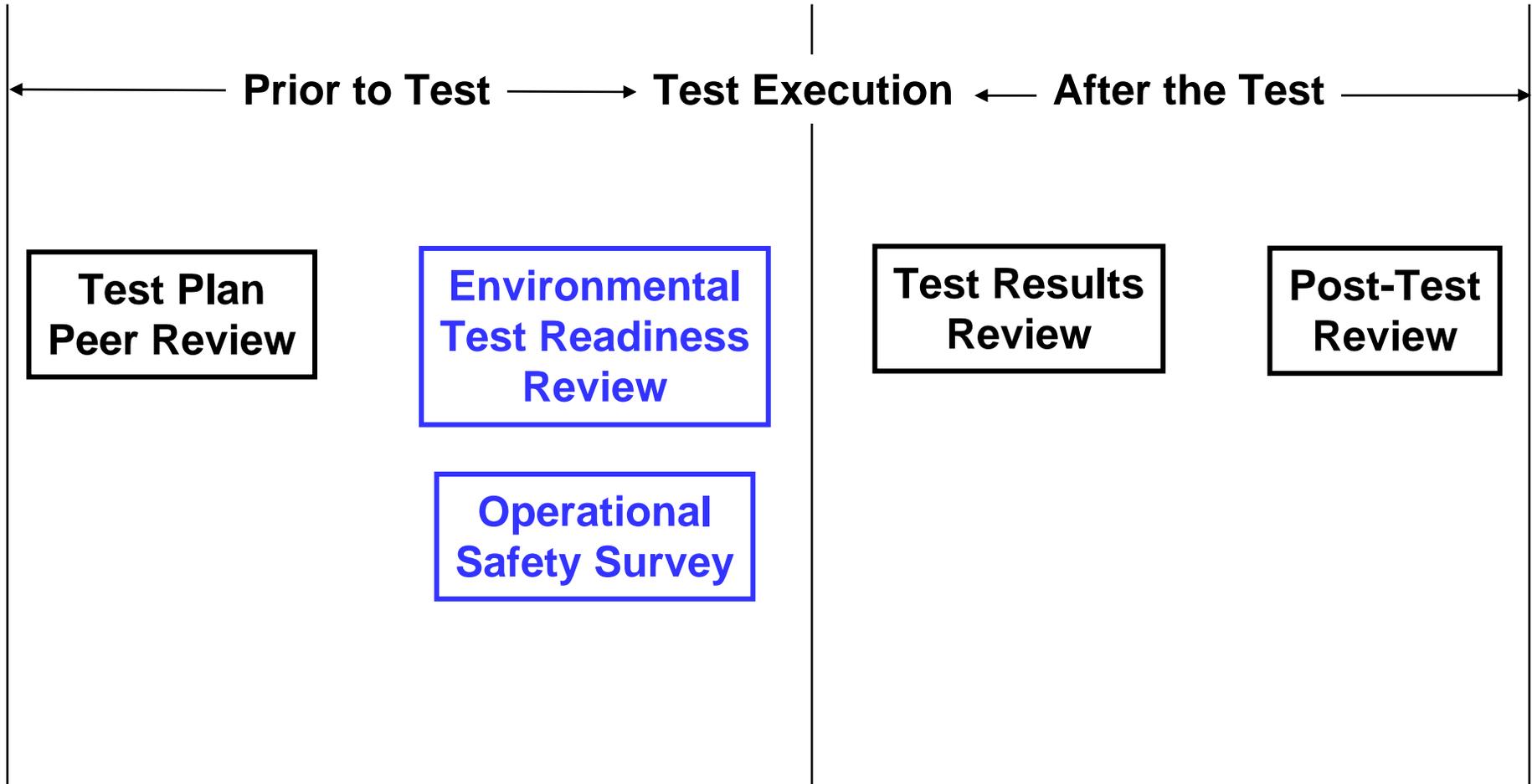


Cassini STV Test Phase 1 Event Timeline



Event No.	Description
1	S/C Baseline Test
2	Close Chamber
3	Nitrogen Flush
4	Start Cooling Shrouds
5	Turn OFF Purge
6	Configure Power for Case 1A
7	Turn off Heaters TBD for Cooldown Acceleration
8	Configure Power for Case 1B
9	CIRS Interference Test
10	CAPS HV Test
11	CDA Interference Test
12	ISS Interference Test
13	Radar 30 minute Turn-ON
14	RWA 30 minute Turn-ON
15	Turn on Heaters for warm-up acceleration
16	Configure Power for Case 1C
17	CIRS, VIMS & ISS Functional Tests and CIRS Microphonics Test
18	Configure Power for Backfill turn ON Purge

Reviewing Your Test Plan



Blue font indicates required when flight hardware present

Test Execution Considerations



- **Effective use of available workforce**
 - Use your discretion to determine if a test must be run around-the-clock
 - Identify primary & relief monitoring workforce
 - Identify test shift lead & communicate this information to the Facility & Integration/Test personnel
 - Ideally, limit each engineer to 1 shift for no longer than 5 consecutive days, followed by 2 non-working days
 - Critical events may warrant increased staffing
- **Criteria for attainment of steady-state**
 - Criteria should be used only as a guide
 - JPL has considered $<0.3^{\circ}\text{C}$ per hour for 3 consecutive hours
 - The responsible thermal test engineer shall use his/her discretion to determine when thermal equilibrium has been sufficiently approached
- **Develop a prioritized emergency contact list & post at monitoring workstation**

Communication Ensures Good Test Coordination



- **As the responsible thermal test engineer, you must ensure that the test is performed within budget & schedule**
 - Confirm that test stakeholders are aware of & buy-in to your approaches & methods
 - When multiple interfaces are involved, you should initiate regular meetings to stay on top of & help resolve any issues
- **Communicate regularly with mechanical and/or electrical fabrication personnel, especially during the fabrication process**
- **Maintain a presence in the Integration & Test arena since this activity is “fast & furious”**
 - Decisions are sometimes made informally & quickly
 - “Out of sight; out of mind”
 - A dedicated thermal engineer for this purpose is ideal

Be Proactive: Contingency Planning

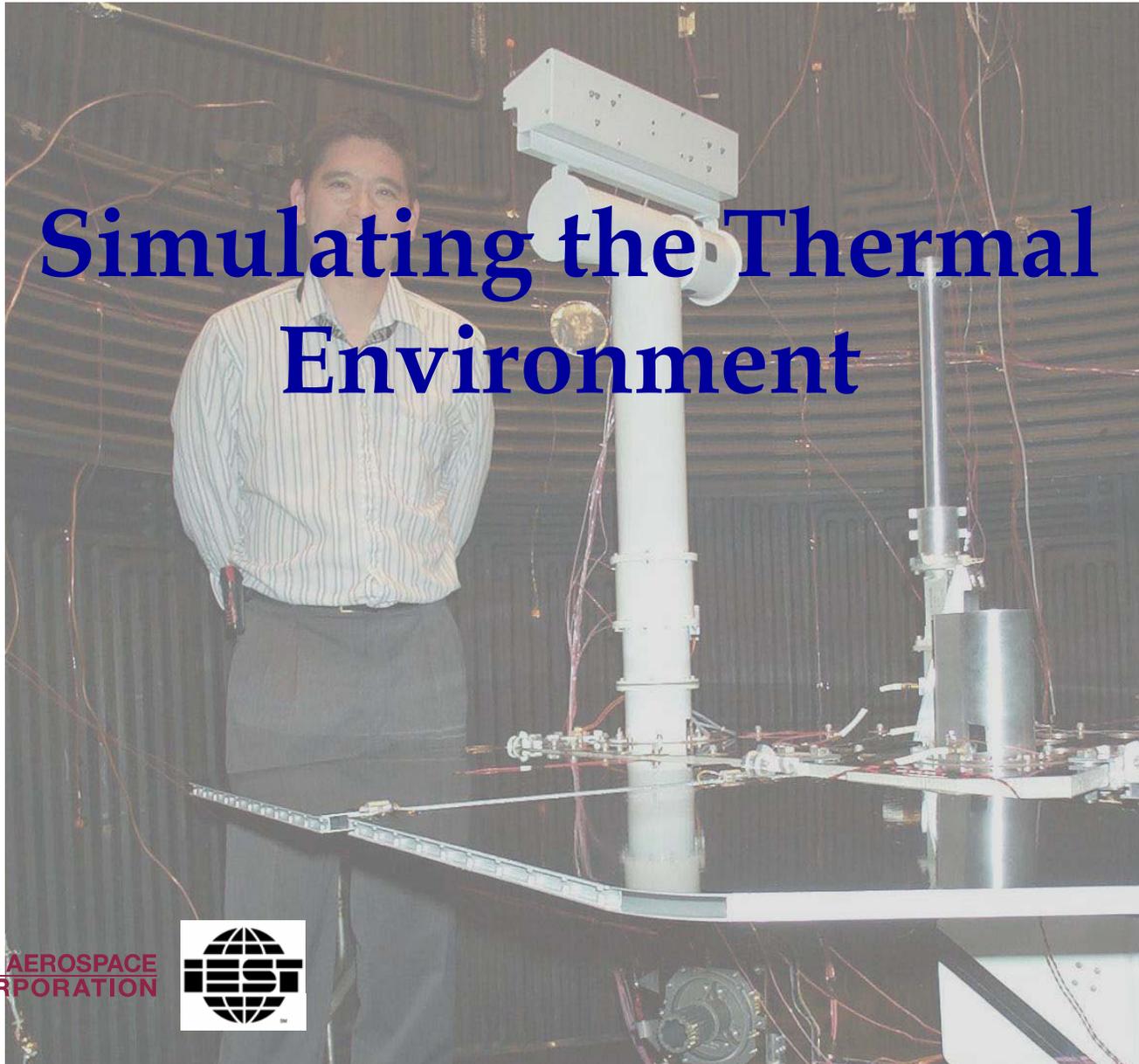


- **Consider design weaknesses that may be uncovered as deficient**
 - **Develop a list of problems that may be encountered & how you would respond to them**
 - **With & without breaking chamber, what additional testing could be performed?**
 - **Provide schedule margin to recover from a design deficiency**
 - **Could some design feature be included in the test setup to provide flexibility?**
 - **Provide more required radiator area or heater power**
 - **Identify “gotta have” test cases versus “wanna have” test cases**
 - **Recovery from a deficiency may result in deletion of test cases to meet Project schedule**

- **Consider the opposite where the test goes faster than expected**
 - **What additional testing would provide high value?**

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Simulating the Thermal Environment



Considerations for Simulating the Thermal Environment



- **Your goal should be focused on the pure simulation of the expected environment**
 - For thermal balance testing, the test would provide an empirical validation of the thermal design
 - In the case of acceptance and/or qualification testing, your focus should be meeting the specified temperature level (& possibly, spatial uniformity) without exception
- **This may be impractical due to several reasons for thermal balance testing**
 - Complex time-varying environment
 - Facility limitations
- **When pure simulation is impractical for thermal balance testing, knowledge of the simulated environment becomes as important as how the environment is simulated**
 - You will be reliant upon an analytical model for design validation
 - The test data will be used to adjust the analytical model

List of Environmental Simulation Tools

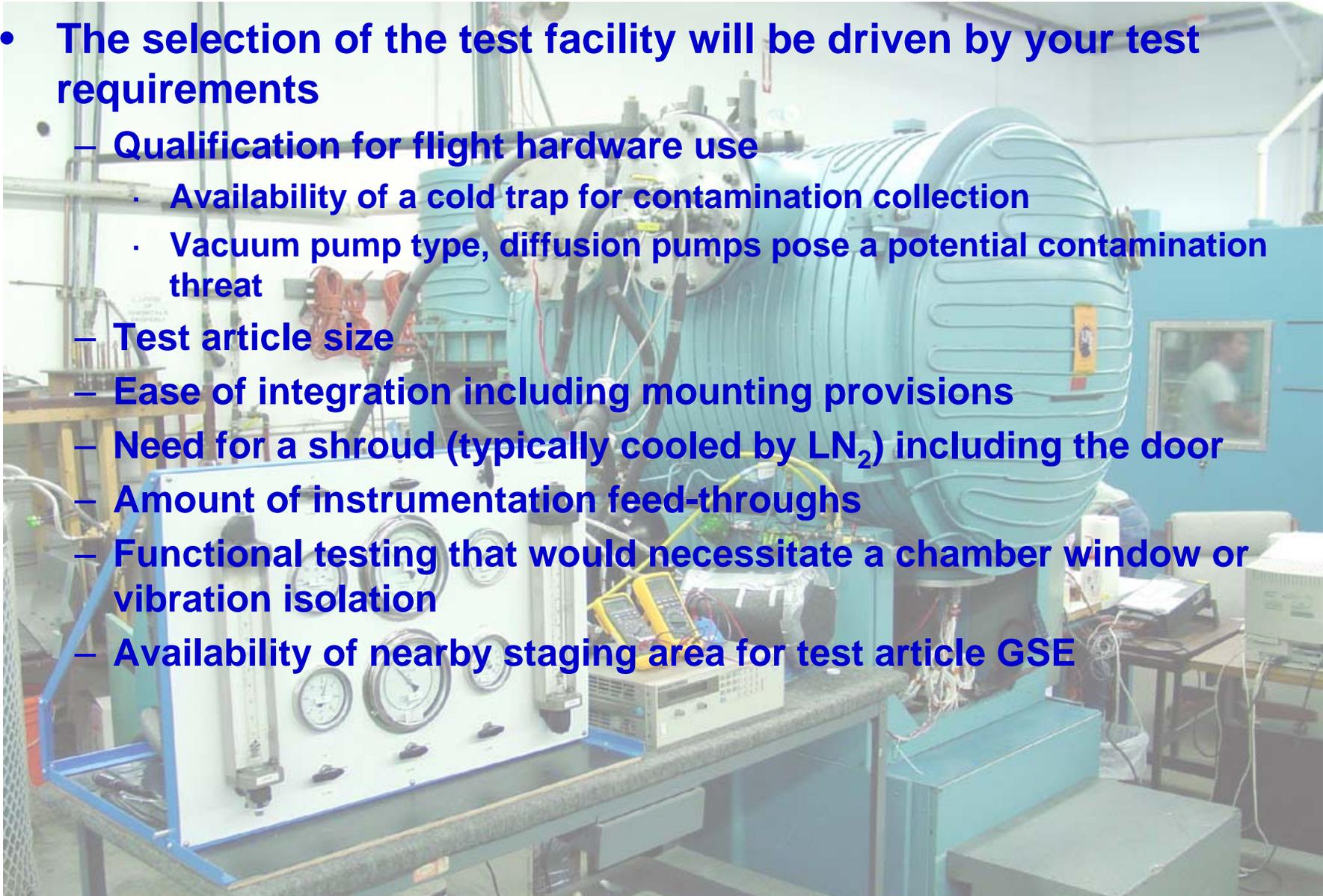


- **Environmental Chambers**
- **Environmental Chamber Shrouds**
- **Conductive & Radiative Boundary Conditions**
 - **Cold Plates & Cold Targets**
 - **Heater Plates**
 - **Achieving Stable Temperature Control**
- **Test Heaters**
- **Solar Simulators (Xenon lamps)**
- **IR Quartz Lamps**
- **Dewars (Cryogenics)**

Environmental Chambers



- **The selection of the test facility will be driven by your test requirements**
 - **Qualification for flight hardware use**
 - Availability of a cold trap for contamination collection
 - Vacuum pump type, diffusion pumps pose a potential contamination threat
 - **Test article size**
 - **Ease of integration including mounting provisions**
 - **Need for a shroud (typically cooled by LN₂) including the door**
 - **Amount of instrumentation feed-throughs**
 - **Functional testing that would necessitate a chamber window or vibration isolation**
 - **Availability of nearby staging area for test article GSE**



Environmental Chamber Shrouds

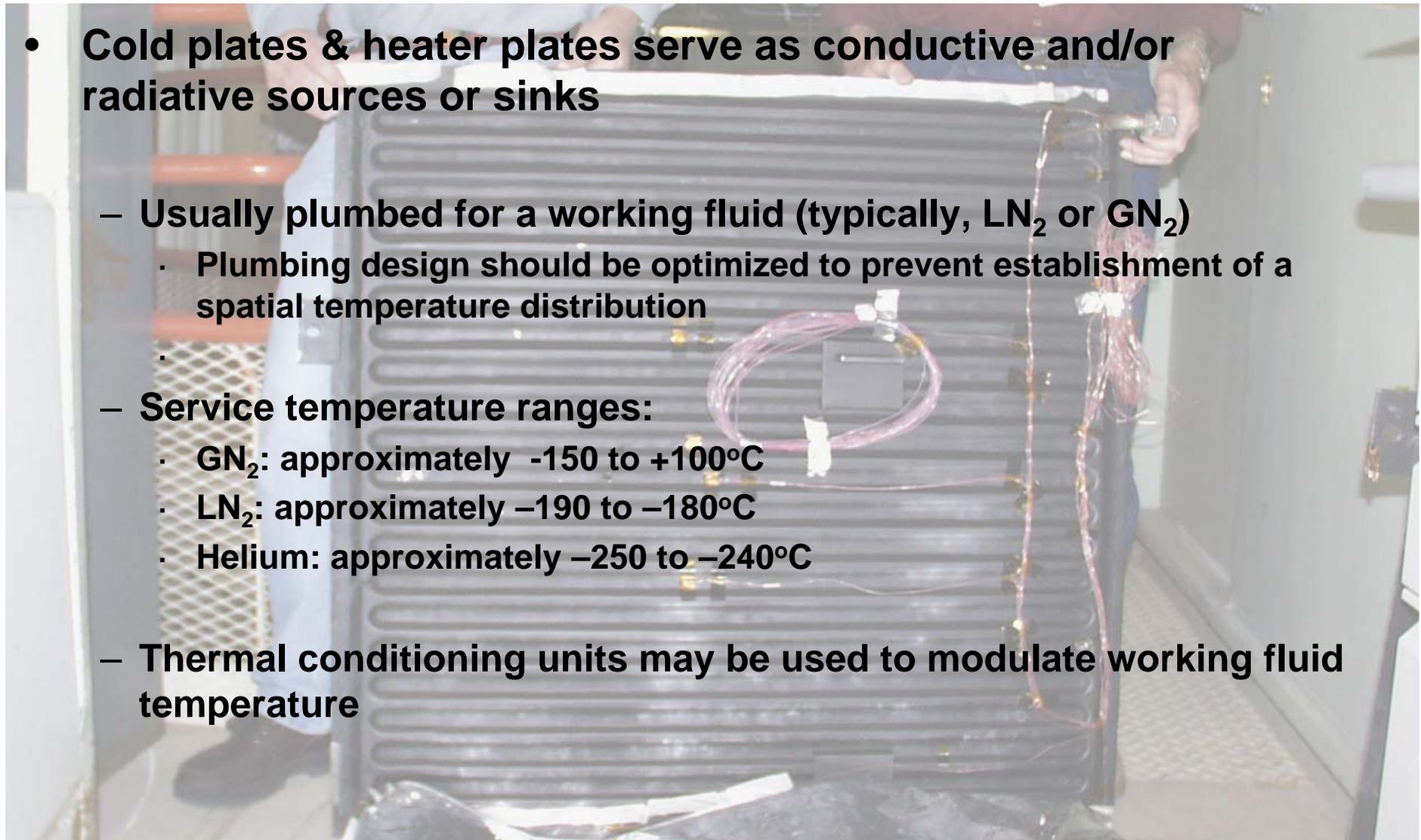


- **Typically, shrouds are used to replicate a radiative boundary condition**
 - For thermal balance test, shrouds usually represent deep space
 - Use of shrouds is usually optional for acceptance and/or qualification testing since flight environment simulation is not performed
 - Understand the control range of shroud temperature capability
 - Flooded with liquid nitrogen, (LN₂ approximately -190 to -170° C)
 - Controlled with gaseous nitrogen (GN₂ approx. -100 to +100° C)
- **Strive to understand how the shroud may interact with the rest of your test setup**
 - Solar simulator reflections
 - If shrouds are cooled to cryogenic temperatures, how does the shroud emittance decrease from its room temperature value?
- **Large chambers require multiple shrouds**
 - Temperature uniformity requirements may lead you to more instrumentation and/or to understand the shroud plumbing schematic

Conductive & Radiative Boundary Conditions (1/2)



- **Cold plates & heater plates serve as conductive and/or radiative sources or sinks**
 - **Usually plumbed for a working fluid (typically, LN₂ or GN₂)**
 - **Plumbing design should be optimized to prevent establishment of a spatial temperature distribution**
 -
 - **Service temperature ranges:**
 - **GN₂: approximately -150 to +100°C**
 - **LN₂: approximately -190 to -180°C**
 - **Helium: approximately -250 to -240°C**
 - **Thermal conditioning units may be used to modulate working fluid temperature**



Conductive & Radiative Boundary Conditions (2/2)

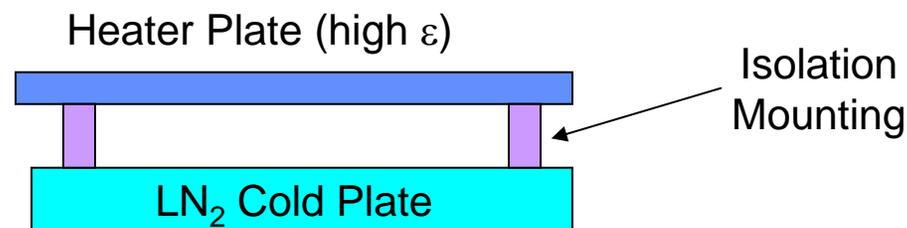


- **Cold targets are special cold plates that act as radiative sinks for radiators or sensing apertures**
 - **Black, open-faced honeycomb may be used to increase effective emittance**
- **Heater plates are usually made from high thermal conductivity material to provide a uniform temperature**
- **Motor-driven louvers can be employed to modulate IR heat flux to or from a cold plate or heater plate**
- **Black (high emittance) finish usually preferred**

Archiving Stable Temperature Control



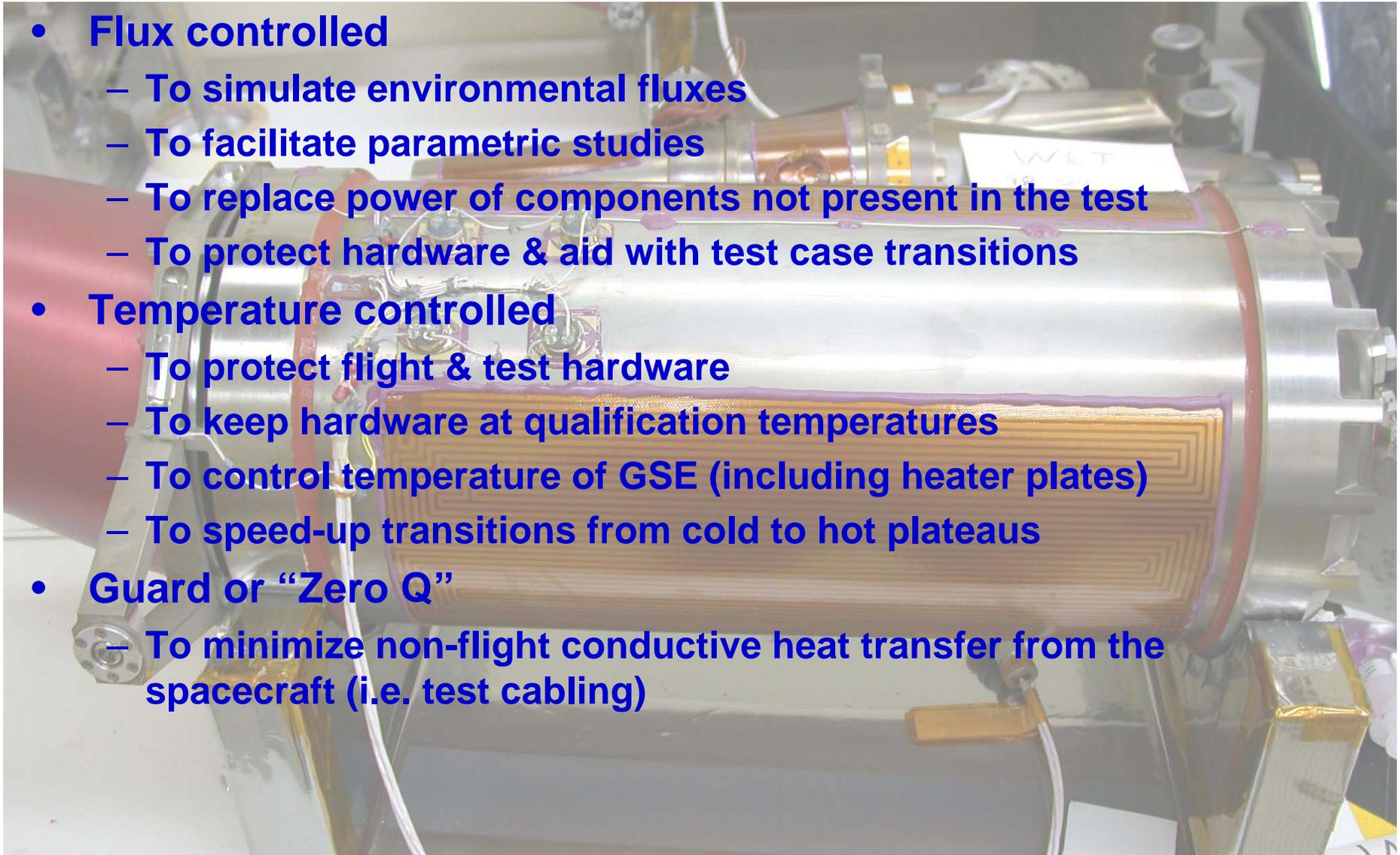
- **Stable boundary temperatures are difficult to attain with a flowing working fluid when goal temperature is significantly greater than phase transition temperature of the working fluid**
 - **Control system becomes a “stiff” situation (i.e., highly sensitive to change in temperature) for the thermal conditioning unit**
 - **This situation can be avoided with a slight design modification**
 - **Control cold plate near phase transition temperature OR more stable goal temperature**
 - **Mount a heater plate with appropriate conductive isolation**
 - **Apply sufficient heater power to meet goal temperature**



Test Heaters



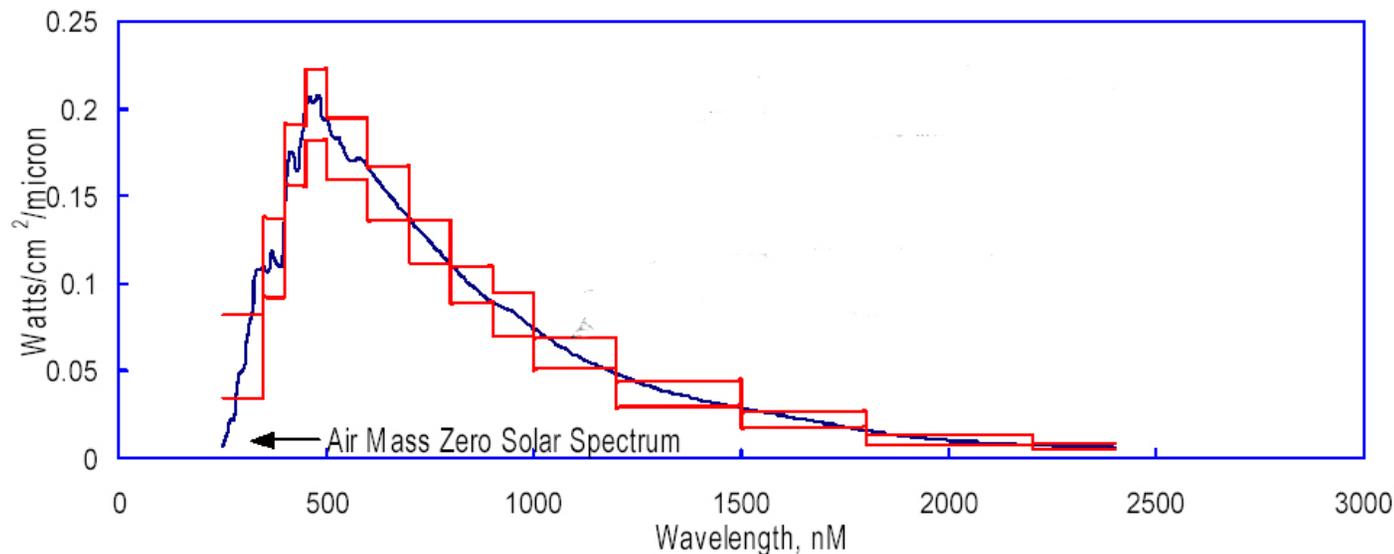
- **Flux controlled**
 - To simulate environmental fluxes
 - To facilitate parametric studies
 - To replace power of components not present in the test
 - To protect hardware & aid with test case transitions
- **Temperature controlled**
 - To protect flight & test hardware
 - To keep hardware at qualification temperatures
 - To control temperature of GSE (including heater plates)
 - To speed-up transitions from cold to hot plateaus
- **Guard or “Zero Q”**
 - To minimize non-flight conductive heat transfer from the spacecraft (i.e. test cabling)



Solar Simulators (1/2)



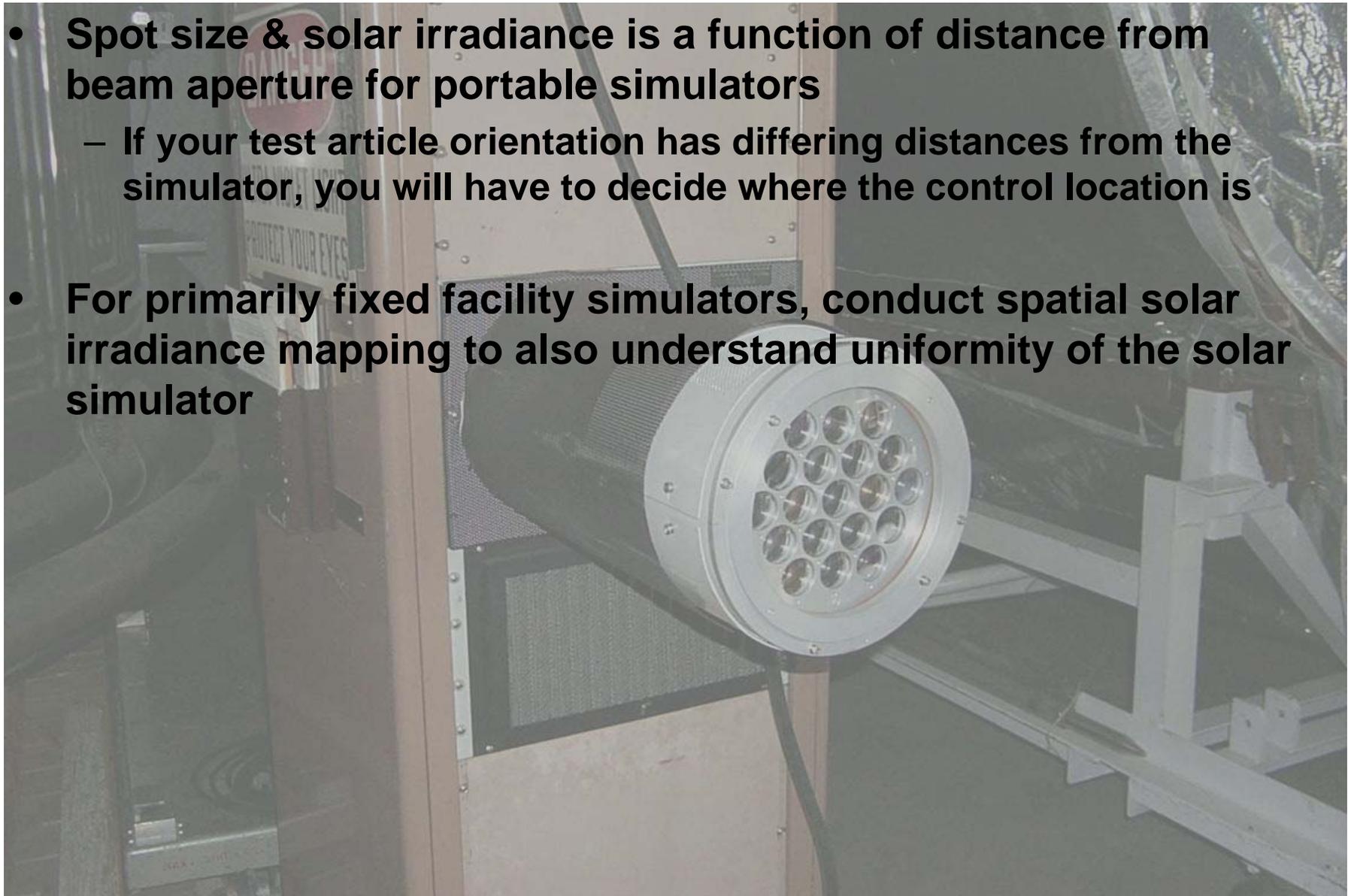
- **Solar simulation is essential for complex geometries where multiple reflections and/or trapping is evident**
- **Two primary Xenon arc lamp types : portable & large fixed facility**
- **Solar simulators approximate the spectral distribution of solar radiation**
 - **Understand how well the spectral distribution is represented**
 - **Thermal control surfaces such as white paints may absorb a different amount of heating than flight**



Solar Simulators (2/2)



- **Spot size & solar irradiance is a function of distance from beam aperture for portable simulators**
 - If your test article orientation has differing distances from the simulator, you will have to decide where the control location is
- **For primarily fixed facility simulators, conduct spatial solar irradiance mapping to also understand uniformity of the solar simulator**



IR Quartz Lamps

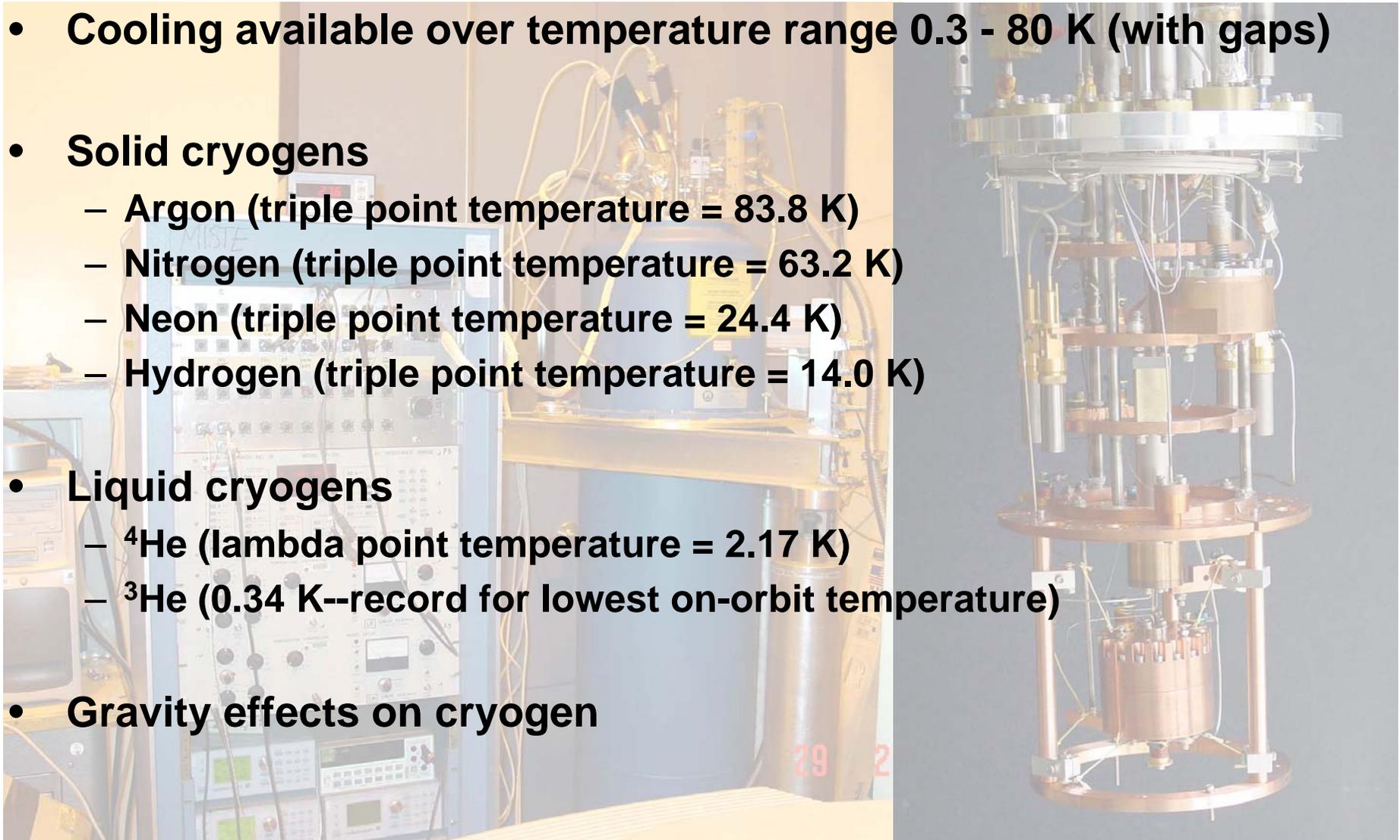


- **IR quartz lamps provide additional flexibility for environmental flux simulation**
 - **Fixtures can be fabricated to provide appropriate directionality including spin-stabilization environments**
 - **Strive for flux uniformity with appropriate lamp spacing**
 - **Judicious use of calorimeters will enable certain quantification of the absorbed heat flux**
 - **Set aside appropriate budget & schedule to identify, fabricate, & calibrate calorimeters**
 - **Lamps are usually grouped into control zones**
 - **May be limited by number of controllers (electronics)**
 - **Give yourself enough flexibility to provide margin beyond expected simulated environment**
 - **Allocate resources to conduct spatial flux mapping**
- **Although there is a small UV flux component, IR lamps lack the ability to replicate solar trapping**

Dewars (Cryogenics)



- **Cooling available over temperature range 0.3 - 80 K (with gaps)**
- **Solid cryogenics**
 - Argon (triple point temperature = 83.8 K)
 - Nitrogen (triple point temperature = 63.2 K)
 - Neon (triple point temperature = 24.4 K)
 - Hydrogen (triple point temperature = 14.0 K)
- **Liquid cryogenics**
 - ^4He (lambda point temperature = 2.17 K)
 - ^3He (0.34 K--record for lowest on-orbit temperature)
- **Gravity effects on cryogen**



22st Aerospace Testing Seminar

March 21, 2005



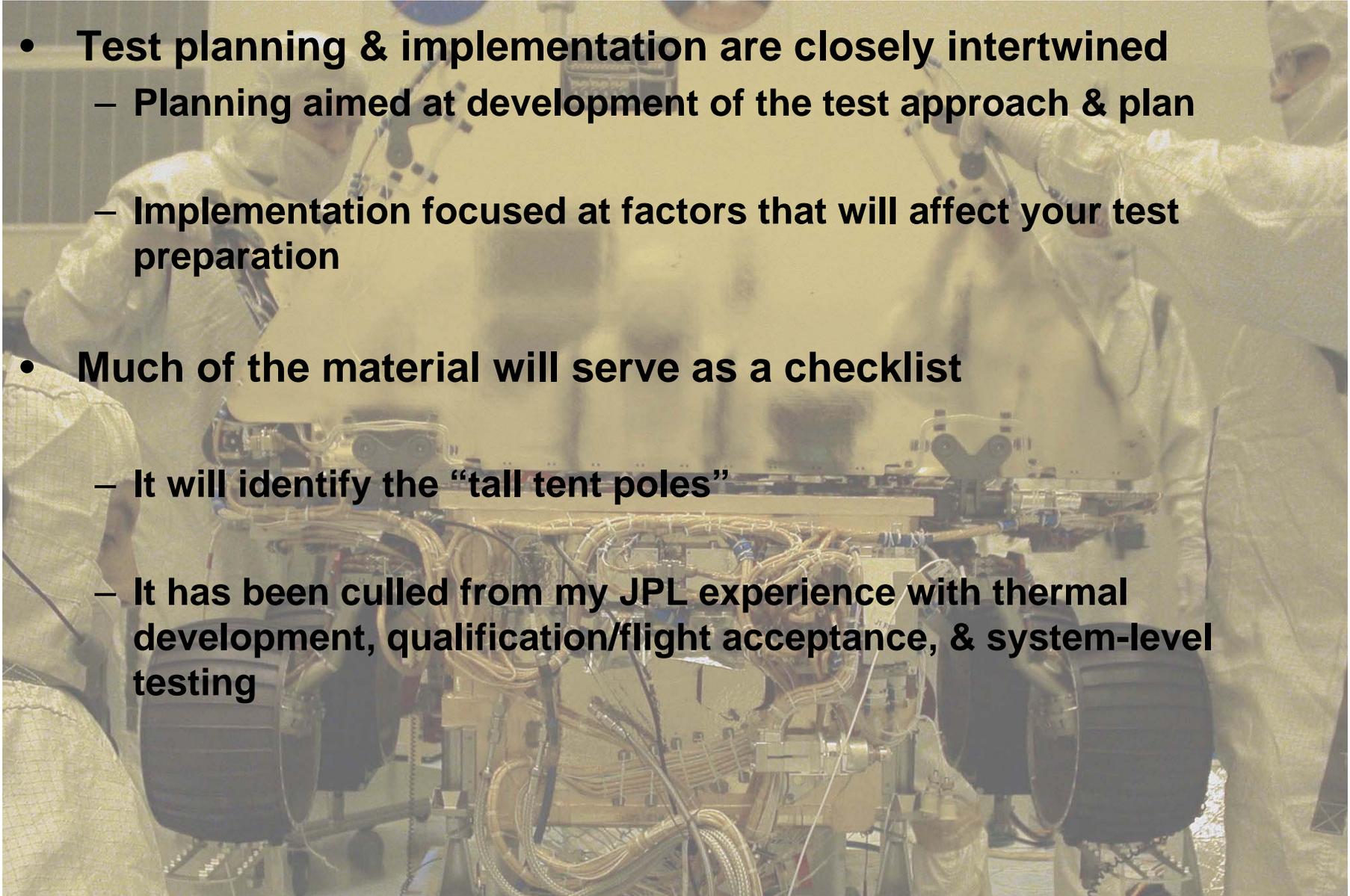
 THE AEROSPACE CORPORATION



Introduction



- **Test planning & implementation are closely intertwined**
 - Planning aimed at development of the test approach & plan
 - Implementation focused at factors that will affect your test preparation
- **Much of the material will serve as a checklist**
 - It will identify the “tall tent poles”
 - It has been culled from my JPL experience with thermal development, qualification/flight acceptance, & system-level testing



“Sharpen Your Saw”

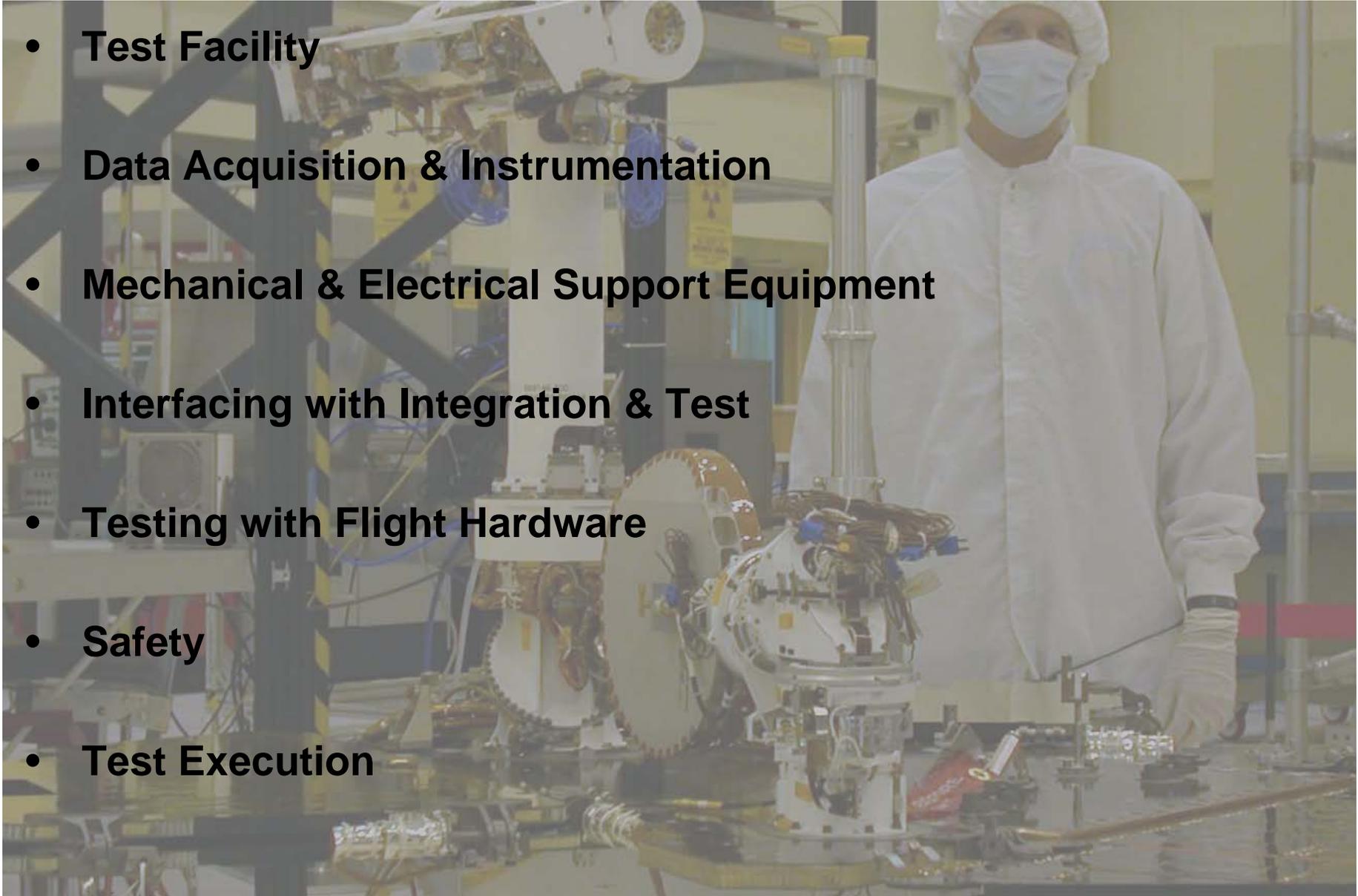


- **You are responsible for overseeing a multitude of tasks & issues covering a wide spectrum of interfaces**
 - A process for proactively addressing & attending to each task is essential
 - Prioritized task list that is reviewed daily
 - War charts
 - Daily logbook
- **You should know the working style of your team & interfaces**
 - Leverage on strengths
 - What is their preferred method of communication?
 - Avoid springing “surprises”
 - Who requires more of your attention & who can be given a “long leash?”
- **You should be familiar your institutional and/or project procedures for conducting tests**

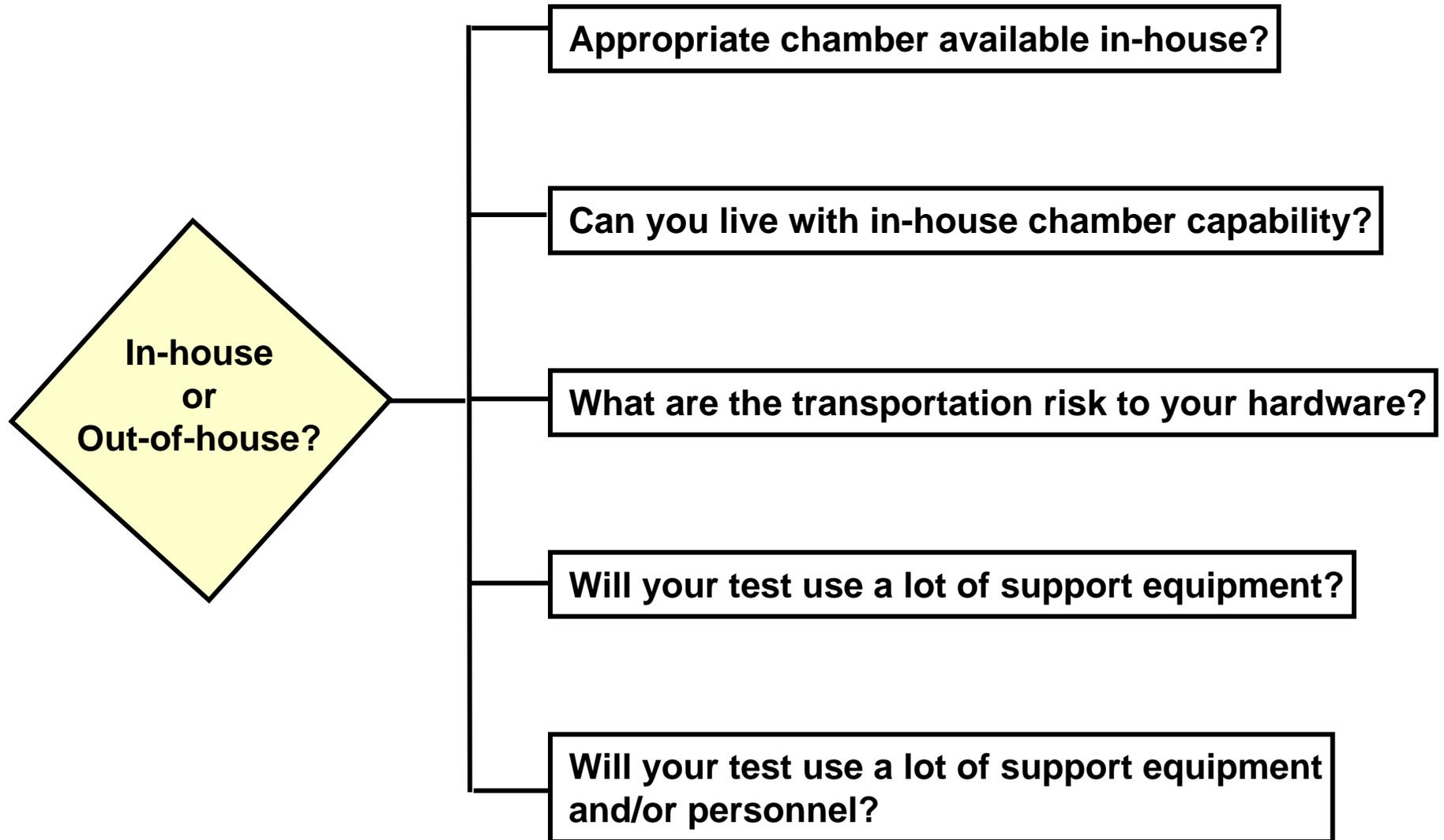
Prioritized Focus Areas



- **Test Facility**
- **Data Acquisition & Instrumentation**
- **Mechanical & Electrical Support Equipment**
- **Interfacing with Integration & Test**
- **Testing with Flight Hardware**
- **Safety**
- **Test Execution**



Where Should You Test?



Chamber Facility's Role



- **Go through the process to schedule your test on the facility schedule**
 - Do it as soon as you know a credible date
 - Make them aware of your schedule changes immediately
- **The facility usually generates their own test procedure**
 - Provide your test matrix including chamber condition requirements
 - Cryogenic cold targets
 - IR lamps
 - Solar simulation lamps
 - Test atmosphere (GN₂ is one typical medium)
 - Shroud temperature (level & rate of change)
 - Contamination monitors
- **A facility dry-run of your test is highly recommended**
 - Especially if chamber has been inoperative for some time

Data Acquisition & Instrumentation (1/5)



- **Data acquisition system**
 - Does it have enough capacity?
 - Temperature channels & power supply telemetry
 - Does it meet your data sampling needs?
 - One entire scan every minutes is usually sufficient
 - Can it perform computations with raw test data?
 - Can it display you data in digital (time-slice) & analog (plot) form?
 - Does it have telemetry alarms (red & yellow)?
 - Provide the data acquisition support group a comprehensive list:
 - Temperature sensors (total number, type, location, alarm limits)
 - Heaters (total number, power, resistance, location, alarm limits)
 - Computed data (formulae)
 - Data display preference (grouping of telemetry for digital or analog display)



- **Temperature instrumentation**
 - **Developing a detailed location map using drawings & photos is essential**
 - **Thermocouple type: Type E, 26 AWG**
 - **Chromel/Constantan recommended to maximize temperature/voltage sensitivity & to minimize parasitic heat leak**
 - **Smaller gauge wire may be needed for very low thermal balance cases**
 - › **These thermocouples are more susceptible to breakage**
 - **Consider redundant thermocouples in critical situations**
 - **Avoid the need for a chamber break in an event of a failure**
 - **Provide sufficient lead time for the installation of thermocouples that are buried inside hardware assemblies**
 - **May result in “clip & fly” approach; may need to consider shielding or grounding open thermocouple**
 - **Place a test thermocouple on every test heater & have its telemetry visible**
 - **For external surface thermocouples, use tape to match actual surface emittance**

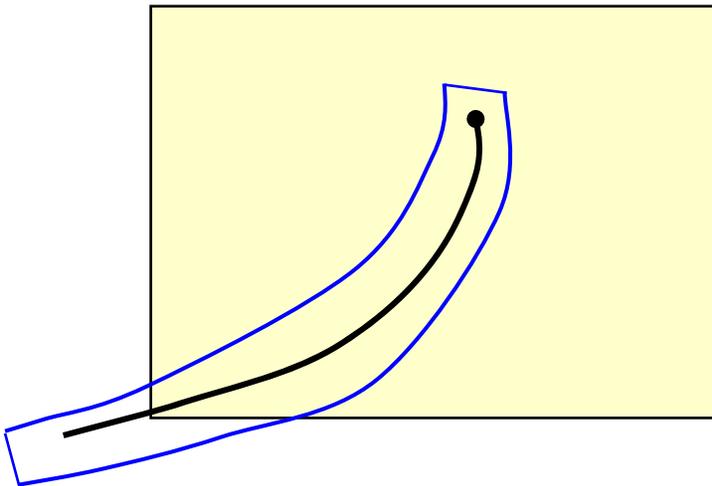


- **Yellow & Red Alarms**

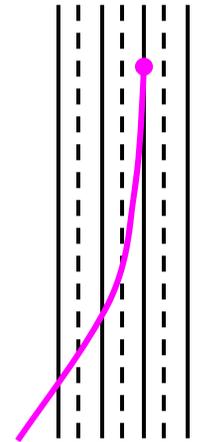
- As a rule of thumb, flight hardware must be maintained within any previous test experience
 - PF/QUAL/FA levels apply
 - Not applicable to PF/QUAL testing OR non-flight thermal control models or mock-ups
- Yellow alarms are generally established as a “warning”
 - Approaching a “hard” limit & intervention by the thermal test engineer may be required to avoid exceedance
 - Particularly useful for thermally isolated & low mass items
- Red alarms are generally defined as “never-to-exceed”
 - FA test level usually apply to flight hardware undergoing system test



- **Thermocouples locally disturb flight-like thermal balance**
 - **Complicates accurate measurement for low heat flow situation (e.g., thermal blankets)**
 - **Minimize non-flight features to the maximum extent practical**



If mounted on an exterior surface, thermally sink thermocouple wire to exterior surface & match exterior surface emittance



If the blanket is non-flight, attach thermocouple to 2nd or 3rd inner layer & route maximum length of wire inside blanket

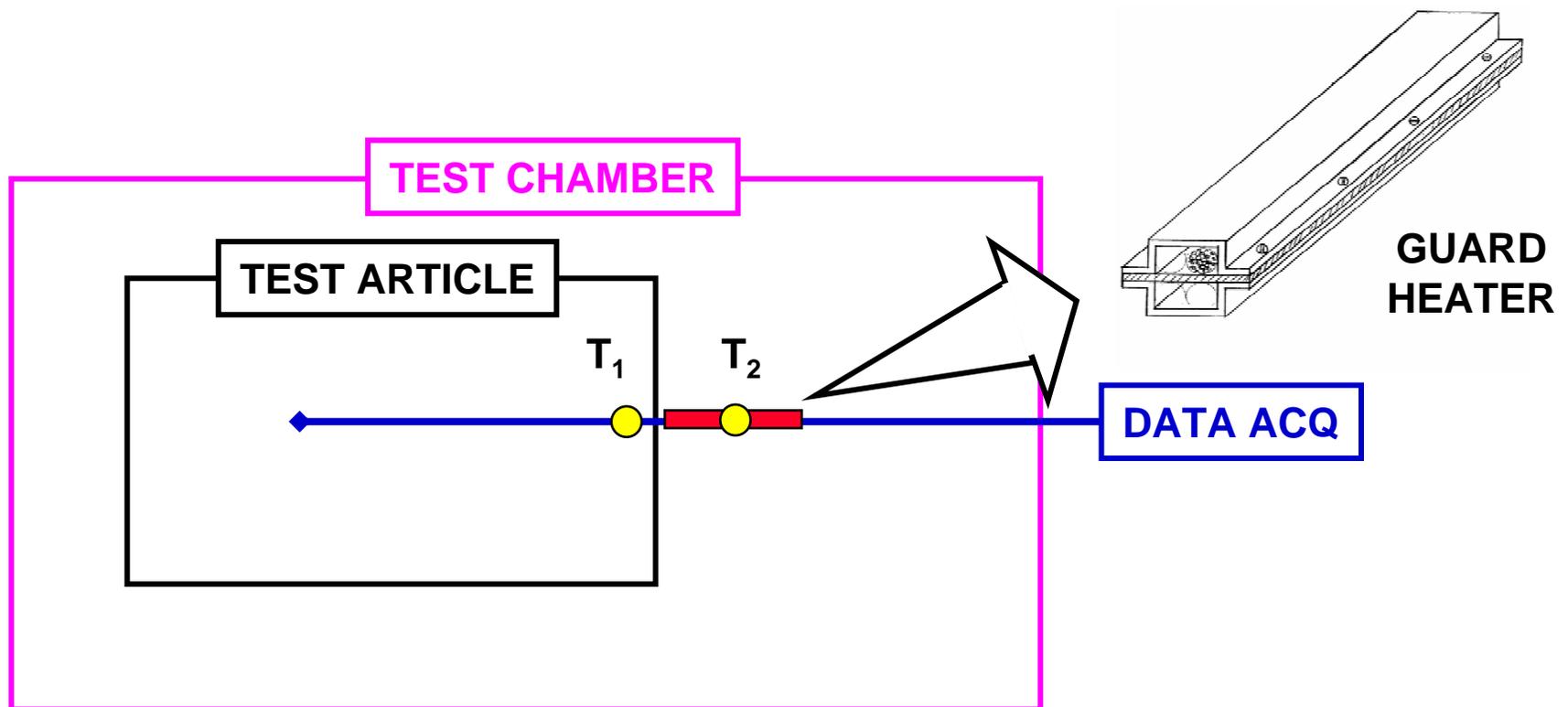


- **Heater instrumentation**

- **Use a 4.0 watt/in² guideline for maximum heater power density without special heat sinking provisions**
 - This is a recommended maximum value when installing test heaters on flight hardware
- **Use test safety or acceleration heaters**
- **Heater lead wire should accommodate worst-case current draw**
- **Explicitly use current and/or voltage limit every power supply regardless of soft crow-bar**
 - Avoid reliance upon soft crow-bars
- **Do you need guard heaters for instrumentation cabling?**



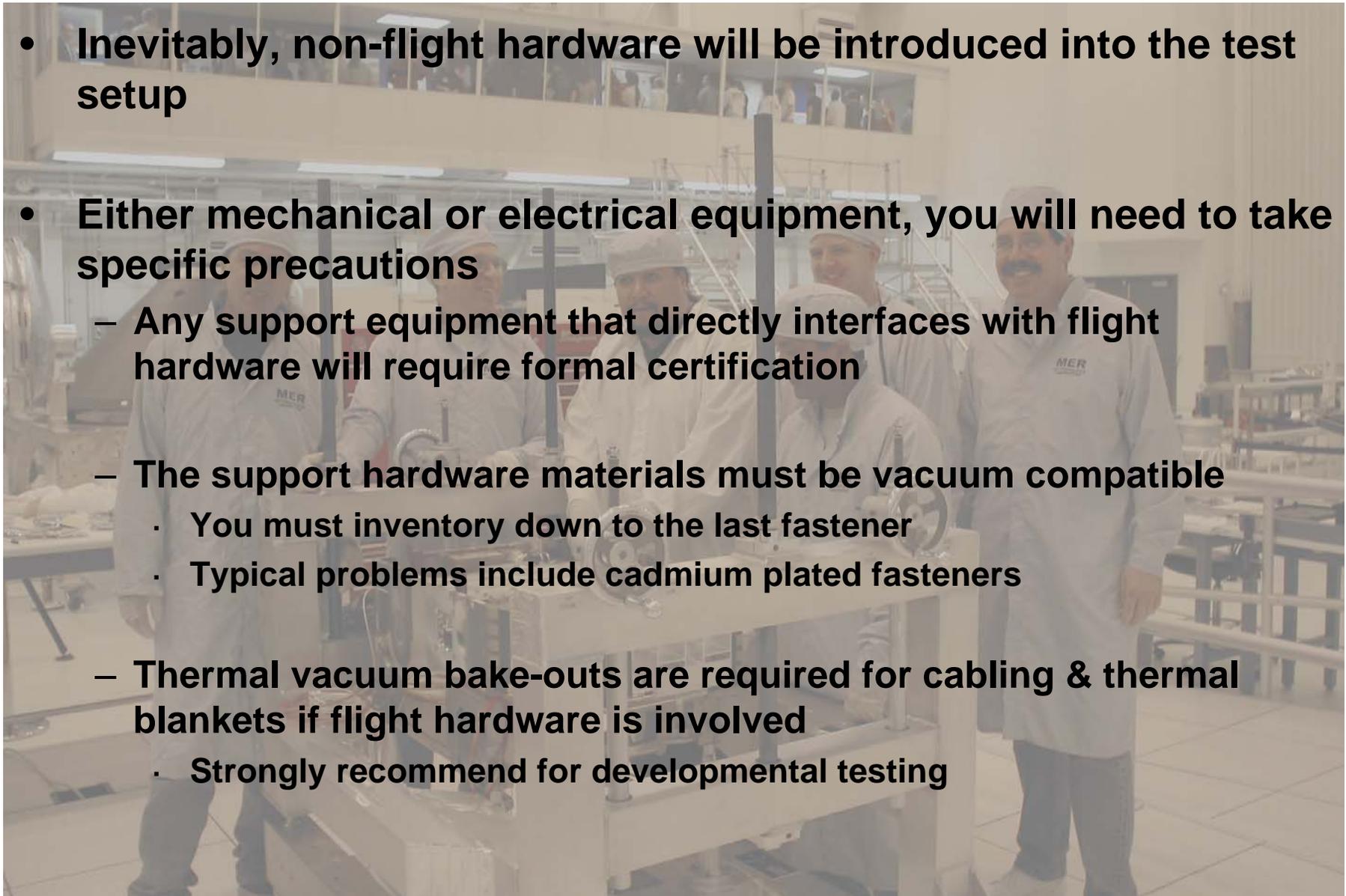
- **Cabling guard heater implementation**
 - The objective is to reduce loss from cabling to chamber
 - This is accomplished by controlling the local heat flow where cabling egresses from test article
 - Apply heater power to guard heater so that $T_1 \approx T_2$



Mechanical & Electrical Support Equipment



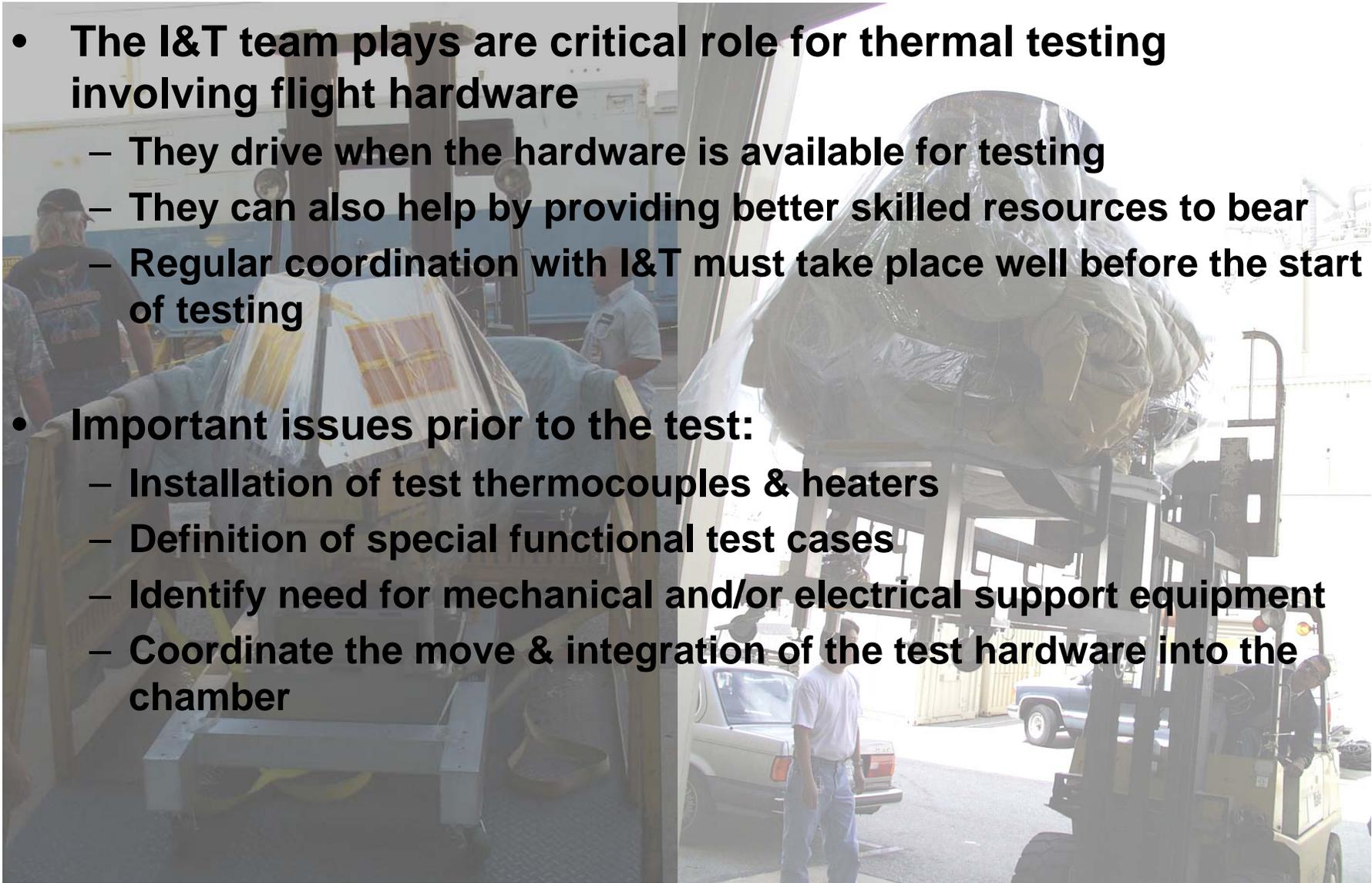
- **Inevitably, non-flight hardware will be introduced into the test setup**
- **Either mechanical or electrical equipment, you will need to take specific precautions**
 - **Any support equipment that directly interfaces with flight hardware will require formal certification**
 - **The support hardware materials must be vacuum compatible**
 - You must inventory down to the last fastener
 - Typical problems include cadmium plated fasteners
 - **Thermal vacuum bake-outs are required for cabling & thermal blankets if flight hardware is involved**
 - Strongly recommend for developmental testing



Interfacing with Integration & Test



- **The I&T team plays a critical role for thermal testing involving flight hardware**
 - They drive when the hardware is available for testing
 - They can also help by providing better skilled resources to bear
 - Regular coordination with I&T must take place well before the start of testing
- **Important issues prior to the test:**
 - Installation of test thermocouples & heaters
 - Definition of special functional test cases
 - Identify need for mechanical and/or electrical support equipment
 - Coordinate the move & integration of the test hardware into the chamber



Testing with Flight Hardware



- **Use of flight hardware in any test must be accompanied with a heightened awareness**
 - **Your primary focus is the safeguarding of the hardware**
 - **Whether working on it OR not!**
 - **You should invoke an end-to-end review of the risks that the hardware will be exposed to prior to, during, and after the test**
 - **You must receive buy-in from the cognizant hardware engineer that these risks are reasonable & acceptable**
 - **Lack of budget & schedule are poor reasons to incur risk**
 - **You must become familiar & practice procedures for handling flight hardware**
 - **Cleanroom garb**
 - **Electrostatic discharge avoidance**
 - **Contamination avoidance including planetary protection**
 - **Follow approved procedures & ensure presence of Quality Assurance personnel when working on flight hardware**

Safety First!



- **Your other primary focus must be the safety of everyone involved with your test**
 - **Is the test facility certified?**
 - Consider support equipment such as cranes or other hoisting devices
 - **Is your test staffing adequately trained to perform their functions?**
 - “Buddy” system usage
 - Entry into confined spaces
 - Entry into spaces where GN₂ or LN₂ was used
 - **Has test plan/procedure been survey & approved by Safety?**
 - Emergency evacuation procedures
 - Emergency contact information
 - Loss of facility power procedures
 - Loss of data acquisition procedure
 - Loss of facility vacuum procedure

Considerations For Executing the Test (1/2)

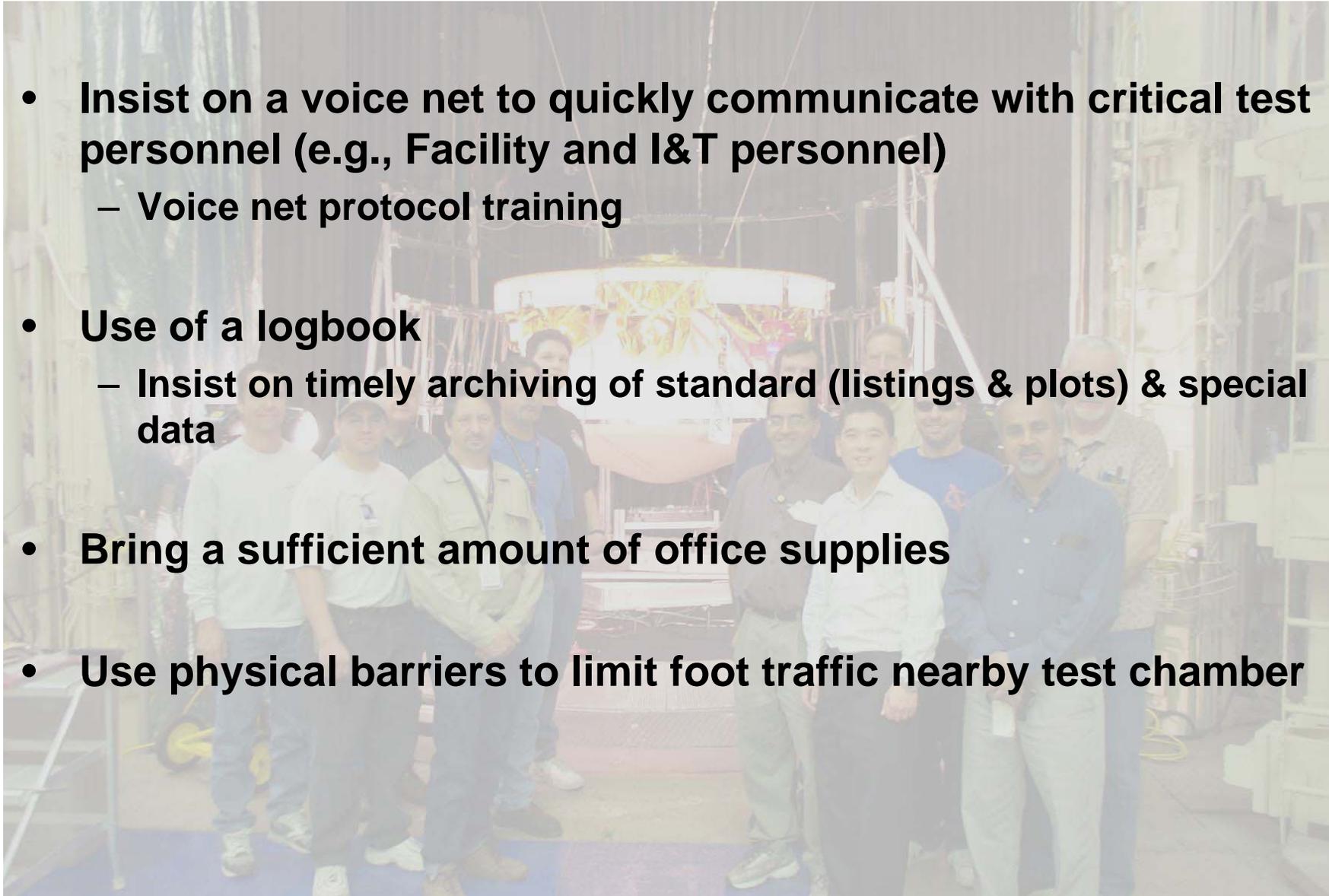


- **Use an optimal test matrix strategy**
 - Rule of Thumb: First test case should be coldest environment & then subsequent case are incrementally warmer
 - Rule of Thumb for critical events: Avoid scheduling critical events during the graveyard shift
 - Use a system engineering approach to all functional verification or validation aspects of the thermal design
 - Seek out input from hardware cognizant engineer or I&T engineers for recommendations for special tests
- **Balanced monitoring workforce to prevent mistakes**
 - Rule of Thumb for around-the-clock testing: 3 shifts with 2 test monitors for a 9-hour duration with an overlap of 1 hour between shifts for a hand-over briefing
 - Provide monitoring relief after 5 consecutive days
- **Ensure your monitoring staff has adequate data acquisition training**
- **Verify that your test instrumentation, including flight telemetry, is functional prior to chamber door closing**

Considerations For Executing the Test (2/2)



- **Insist on a voice net to quickly communicate with critical test personnel (e.g., Facility and I&T personnel)**
 - Voice net protocol training
- **Use of a logbook**
 - Insist on timely archiving of standard (listings & plots) & special data
- **Bring a sufficient amount of office supplies**
- **Use physical barriers to limit foot traffic nearby test chamber**



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- **Gilmore, D. (editor) *Spacecraft Thermal Control Handbook, Volume I: Fundamental Technologies*, American Institute of Aeronautics and Astronautics, Inc., Reston, VA, Chapter 19, Thermal Testing, 2002.**